APPLICANT: FANVIL TECHNOLOGY CO., LTD.
ADDRESS: LEVEL 3, BLOCK A, GAOXINQI BUILDING, ANHUA INDUSTRIAL PARK,
QIANJIN 1 ROAD, 35TH DISTRICT, BAO'AN, SHENZHEN, 518101 P.R. CHINA.

MANUFACTURE : FANVIL TECHNOLOGY CO., LTD.
ADDRESS: LEVEL 3, BLOCK A, GAOXINQI BUILDING, ANHUA INDUSTRIAL PARK,
QIANJIN 1 ROAD, 35TH DISTRICT, BAO'AN, SHENZHEN, 518101 P.R. CHINA.

Report on the submitted sample said to be IP VIDEO PHONE BRAND NAME: N/A MODEL: D600

Test Required: 1)As required by client to determine the Lead,Cadmium,Mercury,Chrimium and Bromine content in the submitted sample.

Test Method:

Testing Item	Testing method	Limit
Lead (Pb)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES	1000ppm
Cadmium (Cd)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES	100ppm
Mercury (Hg)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES	1000ppm
Hexavalent Chromium (Cr6+)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-VIS	1000ppm
Polybrominated Biphenyls (PBBs)	With reference to IEC62321/2nd CDV (111/95/CDV) GC-MS	1000ppm
Polybrominated Diphenylethers (PBDEs)	With reference to IEC62321/2nd CDV (111/95/CDV) GS-MS	1000ppm

Results : Please refer to next pages

Conclusion : When tested as specified,the results shown on the report do not exceed the limit in commission decision of 8 June 2011 Directive 2011/65/EU (RoHS 2) on the restriction of the use of certain hazardous substances in electrical and electronic equipment.All data in this report is provided by the manufacture.

Signed for Shenzhen PZD Technology Co.,Ltd.

Mark Yan

APPROVED
PZD Technology

Mark Yan/ Manager

RESULT SUMMARY

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
1	IC AP1534SG	---	---	---	---	---	Declaration
2	PCB	ND	ND	10	ND	ND	Fulfilled
3	FLASH IC DDR	---	---	---	---	---	Declaration
4	MCU IC	---	---	---	---	---	Declaration
5	IC MEDIA	---	---	---	---	---	Declaration
6	IC POWER	---	---	---	---	---	Declaration
7	IC LDO TOREX	---	---	---	---	---	Declaration
8	IC POE POWER	---	---	---	---	---	Declaration
9	OPTICAL COUPLER	ND	ND	ND	ND	ND	Fulfilled
10	IC POWER TLV	---	---	---	---	---	Declaration
11.1	IC AMP-BODY	ND	ND	4	ND	ND	Fulfilled
11.2	PIN	ND	ND	10	ND	---	Fulfilled
12.1	TC/TRANSFORMER-SILICONE RUBBER	ND	ND	ND	ND	ND	Fulfilled
12.2	MAGNETIC WIRE	ND	ND	ND	ND	ND	Fulfilled
12.3	METAL PART	ND	ND	ND	ND	ND	Fulfilled
12.4	CORE	ND	ND	ND	ND	ND	Fulfilled
12.5	SN WIRE	ND	5	55	ND	ND	Fulfilled
13	CRYSTAL	ND	ND	ND	ND	ND	Fulfilled
14	LED	ND	ND	ND	ND	ND	Fulfilled
15.1	SMD DIODE-BODY	ND	ND	78472*	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
15.2	SMD DIODE-PIN	ND	ND	16	ND	---	Fulfilled
16	DIODE	ND	ND	37.7	ND	ND	Fulfilled
17	DIDOE LL34	ND	ND	224200*	ND	ND	Fulfilled
18	IO ESD PROTECTOR	---	---	---	---	---	Declaration
19	BEAD	ND	ND	ND	ND	ND	Fulfilled
20	CEP- PAPER SHEET	ND	ND	15max	ND	ND	Fulfilled
21	ADAPTER JACK	ND	ND	151	ND	---	Fulfilled
22	MLCC	ND	ND	ND	ND	ND	Fulfilled
23	MLCC	ND	ND	ND	ND	ND	Fulfilled
24	MLCC	ND	ND	ND	ND	ND	Fulfilled
25	RESISTOR	ND	ND	354	ND	ND	Fulfilled
26.1	POWER INDUCTOR CD54-CORE	ND	ND	ND	ND	ND	Fulfilled
26.2	SN WIRE	ND	ND	50	ND	ND	Fulfilled
26.3	VARNISH	ND	ND	ND	ND	ND	Fulfilled
27.1	POWER INDUCTOR RH127 SERIES-EPOXY	ND	ND	ND	ND	ND	Fulfilled
27.2	CORE	ND	ND	ND	ND	ND	Fulfilled
27.3	CORE	ND	ND	ND	ND	ND	Fulfilled
27.4	SN WIRE	ND	ND	50	ND	ND	Fulfilled
27.5	VARNISH	ND	ND	ND	ND	ND	Fulfilled
28.1	TRANSFORMER-MAGNETIC WIRE	ND	ND	ND	ND	ND	Fulfilled
28.2	BOBBIN	ND	ND	8	ND	---	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
28.3	CORE	ND	ND	ND	ND	ND	Fulfilled
28.4	TAPE	ND	ND	20	ND	---	Fulfilled
28.5	SN WIRE	ND	ND	ND	ND	ND	Fulfilled
29.1	NETWORK CABLE-COPPER WIRE	ND	ND	ND	ND	ND	Fulfilled
29.2	PLUG	ND	ND	ND	ND	ND	Fulfilled
29.3	PVC PLASTIC	ND	ND	ND	ND	ND	Fulfilled
29.4	COPPER CONTACT	ND	ND	12	ND	ND	Fulfilled
30	MOSFET AND TRANSISTOR	ND	ND	ND	ND	ND	Fulfilled
31	CONNECTOR PIN	ND	ND	37	ND	---	Fulfilled
32	SD CARD CONNECTOR	ND	ND	63max	ND	ND	Fulfilled
33.1	RJ45 AND RJ9 CONNECTOR-PBT	ND	ND	ND	ND	ND	Fulfilled
33.2	COPPER	ND	ND	9	ND	---	Fulfilled
33.3	GOLD WIRE	ND	ND	ND	ND	ND	Fulfilled
34	EAR JACK	ND	ND	151	ND	---	Fulfilled
35.1	USB AND HDMI CONNECTOR-METAL	ND	ND	246	ND	---	Fulfilled
35.2	USB AND HDMI CONNECTOR-COPPER	ND	ND	26	ND	---	Fulfilled
36.1	FPC CONNECTOR-WHITE PLASTIC	ND	ND	6	ND	ND	Fulfilled
36.2	DK-BROWN PLASTIC	ND	ND	6	ND	ND	Fulfilled
36.3	SILVERY METAL	ND	ND	23	ND	---	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
37.1	PH2.54 CONNECTOR-ABS PLASTIC	ND	ND	ND	ND	ND	Declaration
37.2	H53 BRASS PLATE	ND	ND	246	ND	---	Fulfilled
37.3	PIN	ND	ND	37	ND	---	Fulfilled
38	MAIN PCB	ND	ND	3	ND	ND	Fulfilled
39	ABS PLASTIC PA757	ND	ND	ND	ND	ND	Fulfilled
40	ABS PLASTIC PC-110	ND	ND	ND	ND	ND	Fulfilled
41.1	616E-ABS PLASTIC	ND	ND	ND	ND	ND	Fulfilled
41.2	WIRE	ND	ND	14	ND	---	Fulfilled
41.3	PVC PLASTIC BLACK	ND	ND	ND	ND	ND	Fulfilled
41.4	PVC PLASTIC RED	ND	ND	ND	ND	ND	Fulfilled
41.5	H52 BRASS PLATE	ND	ND	346	ND	---	Fulfilled
42	MIC	ND	ND	24	ND	ND	Fulfilled
43	SPONGE	ND	ND	8	ND	ND	Fulfilled
44	RECEIVER	ND	ND	ND	ND	ND	Fulfilled
45	PAD OF RECEIVER	ND	ND	ND	ND	ND	Fulfilled
46	DUST NET	---	---	---	---	---	Declaration
47	METAL BLOCK	ND	ND	ND	ND	---	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
48	SCREW	ND	ND	ND	ND	---	Fulfilled
49	LCD PANEL	---	---	---	---	---	Declaration
50	TOUCH PANEL	ND	ND	ND	ND	ND	Fulfilled
51.1	CAMERA-LENS	ND	ND	ND	ND	ND	Fulfilled
51.2	FPC	ND	ND	ND	ND	ND	Fulfilled
51.3	TLF-204-111	ND	ND	315	ND	ND	Fulfilled
52	SPEAKER	ND	ND	ND	ND	ND	Fulfilled
53.1	FPC CABLE-FILM	ND	ND	10	ND	ND	Fulfilled
53.2	FILM WITH PRINTING	ND	ND	ND	ND	ND	Fulfilled
53.3	BLUE TAPE	ND	ND	ND	ND	ND	Fulfilled
53.4	METAL WIRE	ND	ND	7	ND	---	Fulfilled
54	PET PROTECT FILM	ND	ND	ND	ND	ND	Fulfilled
55	PMMA	ND	ND	ND	ND	ND	Fulfilled
56	MARKING LABEL	ND	ND	ND	ND	ND	Fulfilled
57	ADAPTER	---	---	---	---	---	Fulfilled
58.1	HANDSET WIRE-PVC PLASTIC	ND	ND	ND	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
58.2	COPPER	ND	ND	ND	ND	---	Fulfilled
59	MANUAL PAPER	ND	ND	ND	ND	ND	Fulfilled
60	PACKAGE BAG	ND	ND	ND	ND	ND	Fulfilled
61.1	PACKAGE BOX-PAPER BOARD	ND	ND	ND	ND	ND	Fulfilled
61.2	INK	ND	ND	ND	ND	ND	Fulfilled
61.3	INK (RED,YELLOW,BLUE,BLCAK)	ND	ND	ND	ND	ND	Fulfilled
62	PROTECT FILM FOR LCD	ND	ND	ND	ND	ND	Fulfilled
63	RESISTOR	ND	ND	668	ND	ND	Fulfilled
64	KEY PCB	ND	ND	8	ND	ND	Fulfilled
65.1	LILLTLE MODULE-BACKLIGHT AND POWER	---	---	---	---	---	Declaration
65.2	MLCC Y5V	ND	ND	ND	ND	ND	Fulfilled
65.3	RESISTOR	ND	ND	668	ND	ND	Fulfilled
65.4.1	FPC CONNECTOR-WHITE PLASTIC	ND	ND	6	ND	ND	Fulfilled
65.4.2	DK-BROWN PLASTIC	ND	ND	6	ND	ND	Fulfilled
65.4.3	SILVERY METAL	ND	ND	23	ND	---	Fulfilled
65.5	DIODE	ND	ND	37.7	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
65.6	DIODE BAV99	ND	ND	ND	ND	ND	Fulfilled
65.7	LL34 DIODE	ND	ND	224200*	ND	ND	Fulfilled
65.8.1	POWER INDUCTOR-CORE	ND	ND	ND	ND	ND	Fulfilled
65.8.2	EPOXY	ND	ND	7	ND	ND	Fulfilled
65.8.3	SN WIRE	ND	ND	50	ND	ND	Fulfilled
65.8.4	VARNISH	ND	ND	ND	ND	ND	Fulfilled
66	IMP809 RESET	ND	ND	ND	ND	ND	Fulfilled
67	TI TRANSLATOR	---	---	---	---	---	Declaration
68	AUDIO CODEC	---	---	---	---	---	Declaration
69	ANALOG SWITCH	---	---	---	---	---	Declaration
70	USB PROTECTOR	---	---	---	---	---	Declaration
71	RT9026PSP	---	---	---	---	---	Declaration

*Remark<1>: According to the declaration from client, the source of Lead in specimen 1 could be from the glass material of that cathode ray tubes which is exempted by RoHS regulatory (Directive 2002/95/EC of the European parliament and of The council of 27 January 2003)

Remark
1. Refer to client information from DECLARATION LETTER
2. Refer to client information SGS:CANEC1301213402
3. Refer to client information from DECLARATION LETTER
4 Refer to client information from DECLARATION LETTER
5 Refer to client information from DECLARATION LETTER
6 Refer to client information from DECLARATION LETTER
7 Refer to client information from DECLARATION LETTER
8 Refer to client information from DECLARATION LETTER
9 Refer to client information SGS:CE/2011/B3548
10 Refer to client information from ON SEMICONDUCTOR DECLARATION LETTER
11 Refer to client information from SGS:CANEC1304007111
12.1 Refer to client information ITS:TWNC00215211
12.2 Refer to client information SGS:GZ1102012117/CHEM
12.3 Refer to client information CTI:RLSZD00083749
12.4 Refer to client information CTI:RLSZC000730750002C
12.5 Refer to client information SGS:GZ1010123000/CHEM 55
13 Refer to client information SGS:CANEC1110991605
14 Refer to client information SGS:CE/2011/70009
15. Refer to client information SGS:CANEC0906214109
16 Refer to client information SGS:CE/2011/93472
17 Refer to client information CTI:RLSZD000857290006
18 Refer to client information from DECLARATION LETTER
19 Refer to client information SGS:CE/2011/B2759
20 Refer to client information SGS:CANEC1303384610
21 Refer to client information CTI:RLSZD000849530002
22. Refer to client information SGS:CANEC1110605101

23.Refer to client information SGS:CANEC1110605105
24.Refer to client information SGS:CANEC1110605104
25.Refer to client information SGS:KA/2012/C0588
26.1 Refer to client information CTI:RLSZD000793730001
26.2 Refer to client information SGS:CANEC1111088220
26.3 Refer to client information SGS:CE/2011/45621A
27.1 Refer to client information SGS:CANEC1100043507
27.2 Refer to client information CTI:RLSZD000805800001
27.3 Refer to client information CTI:RLSZD000793730001
27.4 Refer to client information SGS:CANEC1111088220
27.5 Refer to client information SGS:CE/2011/45621A
28.1 Refer to client information SGS:CANEC1103514901
28.2 Refer to client information SGS:CANEC1100755701
28.3 Refer to client information SGS:SHAEC1102191201
28.4 Refer to client information CTI:RLSHD000743510001
28.5 Refer to client information SGS:GZ1102013749/CHEM
29.1Refer to client information SGS:GZ1103025554/CHEM
29.2 Refer to client information SGS:CE/2012/30567B
29.3 Refer to client information CTI:RLSDD000094790003
29.4 Refer to client information SGS: CE/2012/30602B
30 Refer to client information SGS:SHAEC1104701505
31 Refer to client information SGS:CANEC1111180403
32 Refer to client information HONGCAI:SZC11101280423-3
33.1 Refer to client information SGS:CANEC1100504605
33.2 Refer to client information SGS:CANEC1003851902
33.3 Refer to client information SGS:SHAEC1018875501

34.Refer to client information CTI:RLSZD000849530002

35.1 Refer to client information SGS:SHAEC1102754805

35.2 Refer to client information SGS:CANEC1103616502

36.Refer to client information SGS:CANEC1102359101

37.1 Refer to client information CTI:RLSZD000901720001

37.2 Refer to client information SGS:SHAEC1102754805

37.3 Refer to client information SGS:CANEC1111180403

38 Refer to client information SGS:CANEC1101334308

39 Refer to client information SGS:KA/2011/C1706

40 Refer to client information SGS:KA/2011/C1777

41.1 Refer to client information CTI:RLSZD000901720001

41.2 Refer to client information SGS:CANML1111535001

41.3 Refer to client information SGS:GZ1110130454/CHEM

41.4 Refer to client information SGS:CANEC1110204416

41.5 Refer to client information SGS:SHAEC1102754805

42 Refer to client information SGS:CE/2011/22177

43 Refer to client information SGS:GZ1103018611/CHEM

44 Refer to client information SGS:GZ1104044952/CHEM

45 Refer to client information SGS:GZ1103018609/CHEM

46 Refer to client information from DECLARATION LETTER

47 Refer to client information SGS:CANEC0905103201

48 Refer to client information SGS:CANEC0802051302

49 Refer to client information from DECLARATION LETTER

50 Refer to client information CTI:RLSZC00058315C

51.1 Refer to client information SGS:GZ110816760/CHEM

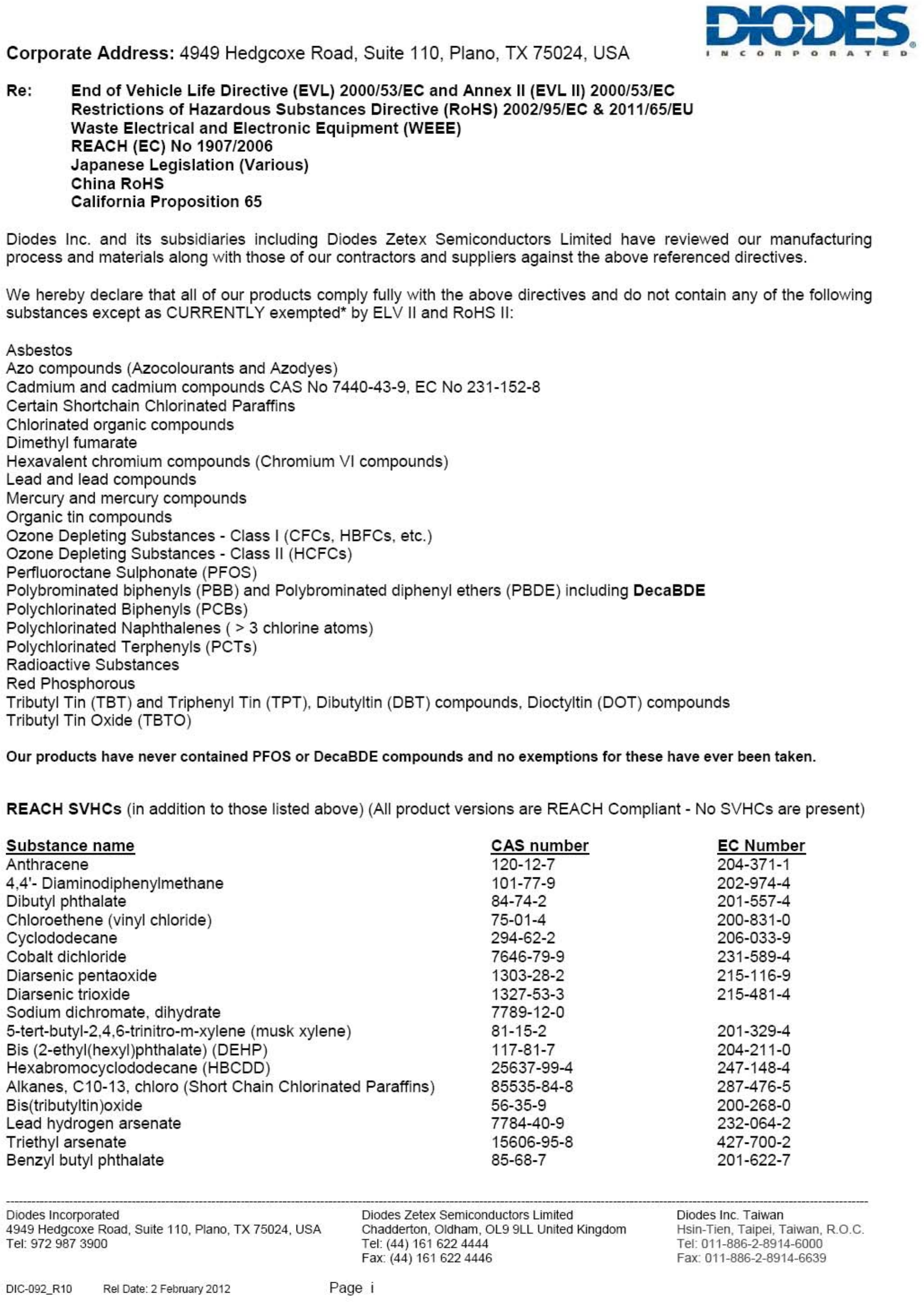
51.2 Refer to client information CTI:RLSZD000993890002C

51.3 Refer to client information SGS:CE/2011/62813
52 Refer to client information SGS:GZ1104044948/CHEM
53 Refer to client information SGS:CANEC1102281001
54 Refer to client information SGS:CANEC1103361102
55 Refer to client information SGS:SHAEC1200148401
56 Refer to client information SGS:SCATR1103000231
57 Refer to client information SGS:GZ1108112408/CHEM
58.1 Refer to client information PONY:E12193012704D
58.2 Refer to client information PONY:E12193012904D
59 Refer to client information SGS:SHAEC1101620904
60 Refer to client information AOV:A001C120210015001-1
61.1 Refer to client information SGS:GZ1011135401/CHEM
61.2 Refer to client information SGS:GZ1103033406/CHEM
61.3 Refer to client information SGS:GZ1103033412/CHEM
62 Refer to client information SGS:GZ1103018609/CHEM
63 Refer to client information SGS:CANEC1102192901
64 Refer to client information SGS:CANEC1101334301
65.1 Refer to client information from MPS DECLARATION LETTER
65.2 Refer to client information SGS:CANEC1110605104
65.3 Refer to client information SGS:CANEC1102192901
65.4 Refer to client information SGS:CANEC1102359101
65.5 Refer to client information SGS:CE/2011/93472
65.6 Refer to client information SGS:SHAEC1104701505
65.7 Refer to client information CTI:RLSZD000857290006
65.8.1 Refer to client information SGS:CANEC1101185901
65.8.2 Refer to client information SGS:CANEC1100321401

65.8.3 Refer to client information SGS:CANEC1111088220 A01
65.8.4 Refer to client information SGS:CE/2011/45621A
66. Refer to client information SGS:NGEC1200158901
67. Refer to client information from TI DECLARATION LETTER
68. Refer to client information from IPC DECLARATION LETTER
69. Refer to client information from NXP DECLARATION LETTER
70. Refer to client information from MICREL DECLARATION LETTER
71. Refer to client information from RICHTEK DECLARATION LETTER

APPENDIX I

DECLARATION LETTER FROM DIODES



Corporate Address: 4949 Hedgcoxe Road, Suite 110, Plano, TX 75024, USA

Re:
End of Vehicle Life Directive (EVL) 2000/53/EC and Annex II (EVL II) 2000/53/EC
Restrictions of Hazardous Substances Directive (RoHS) 2002/95/EC & 2011/65/EU
Waste Electrical and Electronic Equipment (WEEE)
REACH (EC) No 1907/2006
Japanese Legislation (Various)
China RoHS
California Proposition 65

Diodes Inc. and its subsidiaries including Diodes Zetex Semiconductors Limited have reviewed our manufacturing process and materials along with those of our contractors and suppliers against the above referenced directives.

We hereby declare that all of our products comply fully with the above directives and do not contain any of the following substances except as CURRENTLY exempted* by ELV II and RoHS II:

Asbestos
Azo compounds (Azocolourants and Azodyes)
Cadmium and cadmium compounds CAS No 7440-43-9, EC No 231-152-8
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Dimethyl fumarate
Hexavalent chromium compounds (Chromium VI compounds)
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluoroctane Sulphonate (PFOS)
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Polychlorinated Terphenyls (PCTs)
Radioactive Substances
Red Phosphorous
Tributyl Tin (TBT) and Triphenyl Tin (TPT), Dibutyltin (DBT) compounds, Dioctyltin (DOT) compounds
Tributyl Tin Oxide (TBTO)

Our products have never contained PFOS or DecaBDE compounds and no exemptions for these have ever been taken.

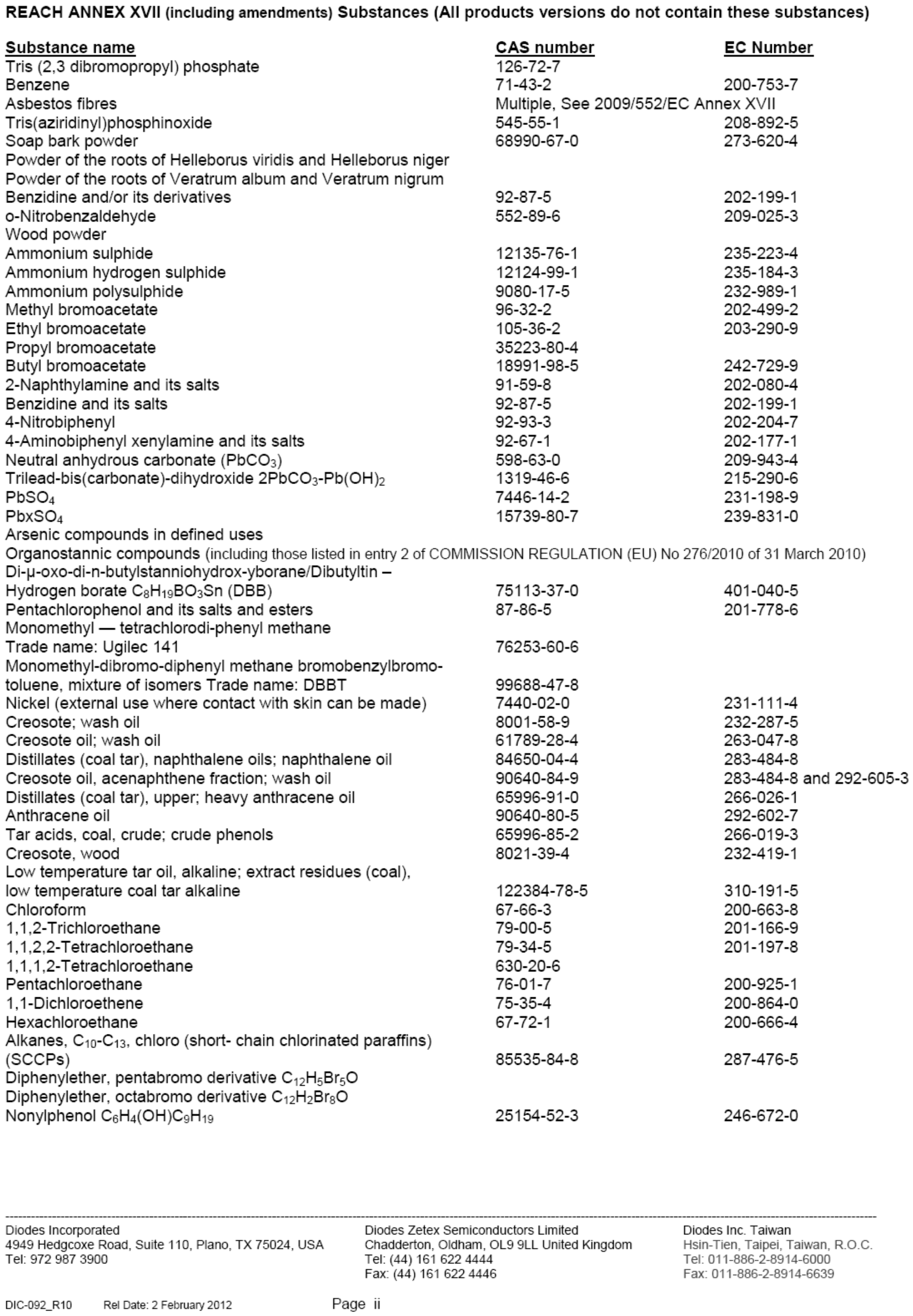
REACH SVHCs (in addition to those listed above) (All product versions are REACH Compliant - No SVHCs are present)

Substance name	CAS number	EC Number
Anthracene	120-12-7	204-371-1
4,4'- Diaminodiphenylmethane	101-77-9	202-974-4
Dibutyl phthalate	84-74-2	201-557-4
Chloroethene (vinyl chloride)	75-01-4	200-831-0
Cyclododecane	294-62-2	206-033-9
Cobalt dichloride	7646-79-9	231-589-4
Diarsenic pentaoxide	1303-28-2	215-116-9
Diarsenic trioxide	1327-53-3	215-481-4
Sodium dichromate, dihydrate	7789-12-0	
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)	81-15-2	201-329-4
Bis (2-ethyl(hexyl)phthalate) (DEHP)	117-81-7	204-211-0
Hexabromocyclododecane (HBCDD)	25637-99-4	247-148-4
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)	85535-84-8	287-476-5
Bis(tributyltin)oxide	56-35-9	200-268-0
Lead hydrogen arsenate	7784-40-9	232-064-2
Triethyl arsenate	15606-95-8	427-700-2
Benzyl butyl phthalate	85-68-7	201-622-7

Diodes Incorporated
4949 Hedgcoxe Road, Suite 110, Plano, TX 75024, USA
Tel: 972 987 3900

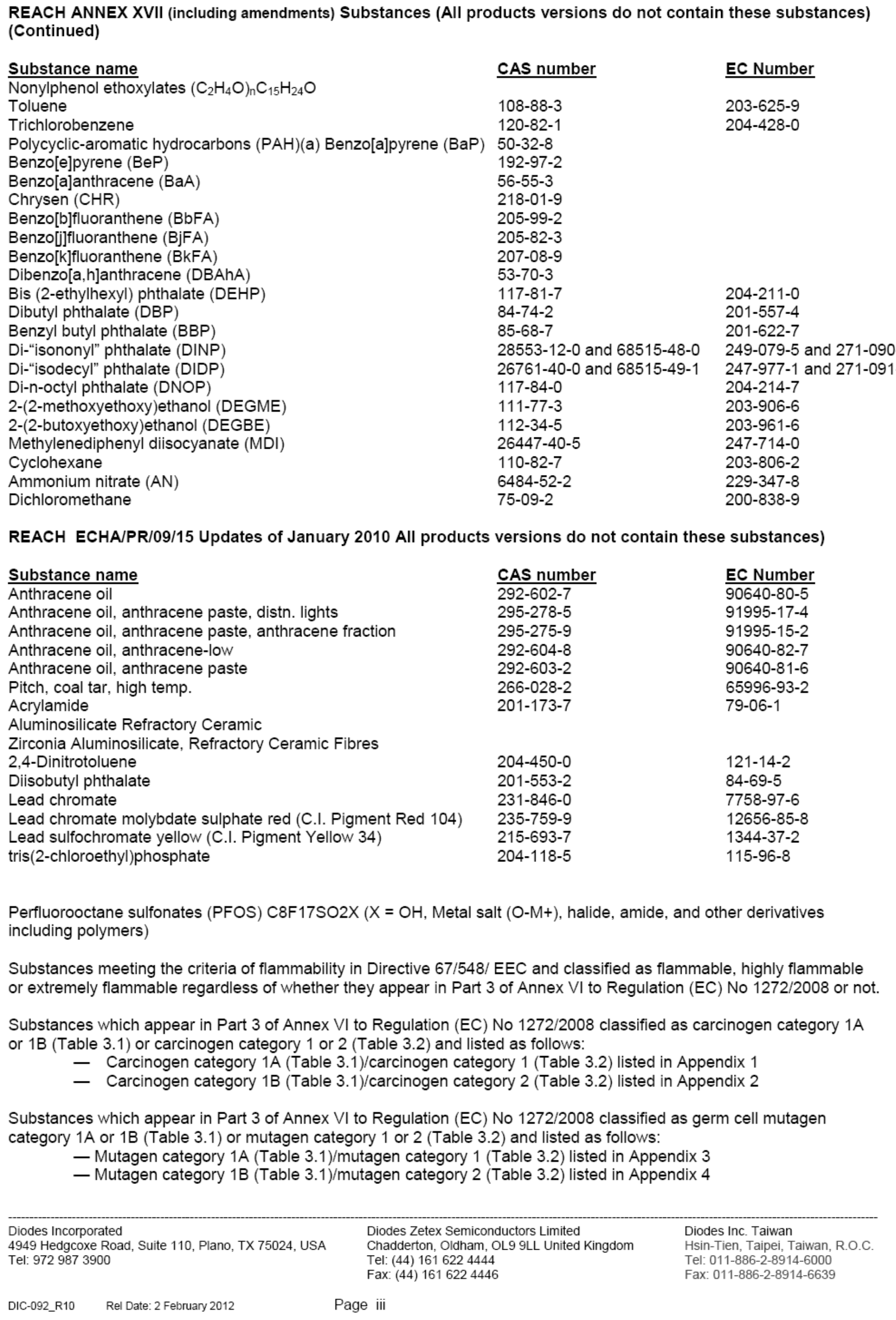
Diodes Zetex Semiconductors Limited
Chadderton, Oldham, OL9 9LL United Kingdom
Tel: (44) 161 622 4444
Fax: (44) 161 622 4446

Diodes Inc. Taiwan
Hsin-Tien, Taipei, Taiwan, R.O.C.
Tel: 011-886-2-8914-6000
Fax: 011-886-2-8914-6639



REACH ANNEX XVII (including amendments) Substances (All products versions do not contain these substances)

Substance name	CAS number	EC Number
Tris (2,3 dibromopropyl) phosphate	126-72-7	
Benzene	71-43-2	200-753-7
Asbestos fibres	Multiple, See 2009/552/EC Annex XVII	
Tris(aziridinyl)phosphinoxide	545-55-1	208-892-5
Soap bark powder	68990-67-0	273-620-4
Powder of the roots of Helleborus viridis and Helleborus niger		
Powder of the roots of Veratrum album and Veratrum nigrum		
Benzidine and/or its derivatives	92-87-5	202-199-1
o-Nitrobenzaldehyde	552-89-6	209-025-3
Wood powder		
Ammonium sulphide	12135-76-1	235-223-4
Ammonium hydrogen sulphide	12124-99-1	235-184-3
Ammonium polysulphide	9080-17-5	232-989-1
Methyl bromoacetate	96-32-2	202-499-2
Ethyl bromoacetate	105-36-2	203-290-9
Propyl bromoacetate	35223-80-4	
Butyl bromoacetate	18991-98-5	242-729-9
2-Naphthylamine and its salts	91-59-8	202-080-4
Benzidine and its salts	92-87-5	202-199-1
4-Nitrobiphenyl	92-93-3	202-204-7
4-Aminobiphenyl xenylamine and its salts	92-67-1	202-177-1
Neutral anhydrous carbonate ($PbCO_3$)	598-63-0	209-943-4
Trilead-bis(carbonate)-dihydroxide $2PbCO_3$-$Pb(OH)_2$	1319-46-6	215-290-6
$PbSO_4$	7446-14-2	231-198-9
$PbxSO_4$	15739-80-7	239-831-0
Arsenic compounds in defined uses		
Organostannic compounds (including those listed in entry 2 of COMMISSION REGULATION (EU) No 276/2010 of 31 March 2010)		
Di-μ-oxo-di-n-butylstanniohydrox-yborane/Dibutyltin – Hydrogen borate $C_8H_{19}BO_3Sn$ (DBB)	75113-37-0	401-040-5
Pentachlorophenol and its salts and esters	87-86-5	201-778-6
Monomethyl — tetrachlorodi-phenyl methane Trade name: Ugilec 141	76253-60-6	
Monomethyl-dibromo-diphenyl methane bromobenzylbromo-toluene, mixture of isomers Trade name: DBBT	99688-47-8	
Nickel (external use where contact with skin can be made)	7440-02-0	231-111-4
Creosote; wash oil	8001-58-9	232-287-5
Creosote oil; wash oil	61789-28-4	263-047-8
Distillates (coal tar), naphthalene oils; naphthalene oil	84650-04-4	283-484-8
Creosote oil, acenaphthene fraction; wash oil	90640-84-9	283-484-8 and 292-605-3
Distillates (coal tar), upper; heavy anthracene oil	65996-91-0	266-026-1
Anthracene oil	90640-80-5	292-602-7
Tar acids, coal, crude; crude phenols	65996-85-2	266-019-3
Creosote, wood	8021-39-4	232-419-1
Low temperature tar oil, alkaline; extract residues (coal), low temperature coal tar alkaline	122384-78-5	310-191-5
Chloroform	67-66-3	200-663-8
1,1,2-Trichloroethane	79-00-5	201-166-9
1,1,2,2-Tetrachloroethane	79-34-5	201-197-8
1,1,1,2-Tetrachloroethane	630-20-6	
Pentachloroethane	76-01-7	200-925-1
1,1-Dichloroethene	75-35-4	200-864-0
Hexachloroethane	67-72-1	200-666-4
Alkanes, C_{10}-C_{13}, chloro (short- chain chlorinated paraffins) (SCCPs)	85535-84-8	287-476-5
Diphenylether, pentabromo derivative $C_{12}H_5Br_5O$		
Diphenylether, octabromo derivative $C_{12}H_2Br_8O$		
Nonylphenol $C_6H_4(OH)C_9H_{19}$	25154-52-3	246-672-0



REACH ANNEX XVII (including amendments) Substances (All products versions do not contain these substances) (Continued)

Substance name	CAS number	EC Number
Nonylphenol ethoxylates $(C_2H_4O)_nC_{15}H_{24}O$		
Toluene	108-88-3	203-625-9
Trichlorobenzene	120-82-1	204-428-0
Polycyclic-aromatic hydrocarbons (PAH)(a) Benzo[a]pyrene (BaP)	50-32-8	
Benzo[e]pyrene (BeP)	192-97-2	
Benzo[a]anthracene (BaA)	56-55-3	
Chrysen (CHR)	218-01-9	
Benzo[b]fluoranthene (BbFA)	205-99-2	
Benzo[j]fluoranthene (BjFA)	205-82-3	
Benzo[k]fluoranthene (BkFA)	207-08-9	
Dibenzo[a,h]anthracene (DBAhA)	53-70-3	
Bis (2-ethylhexyl) phthalate (DEHP)	117-81-7	204-211-0
Dibutyl phthalate (DBP)	84-74-2	201-557-4
Benzyl butyl phthalate (BBP)	85-68-7	201-622-7
Di-"isononyl" phthalate (DINP)	28553-12-0 and 68515-48-0	249-079-5 and 271-090-9
Di-"isodecyl" phthalate (DIDP)	26761-40-0 and 68515-49-1	247-977-1 and 271-091-4
Di-n-octyl phthalate (DNOP)	117-84-0	204-214-7
2-(2-methoxyethoxy)ethanol (DEGME)	111-77-3	203-906-6
2-(2-butoxyethoxy)ethanol (DEGBE)	112-34-5	203-961-6
Methylenediphenyl diisocyanate (MDI)	26447-40-5	247-714-0
Cyclohexane	110-82-7	203-806-2
Ammonium nitrate (AN)	6484-52-2	229-347-8
Dichloromethane	75-09-2	200-838-9

REACH ECHA/PR/09/15 Updates of January 2010 All products versions do not contain these substances)

Substance name	CAS number	EC Number
Anthracene oil	292-602-7	90640-80-5
Anthracene oil, anthracene paste, distn. lights	295-278-5	91995-17-4
Anthracene oil, anthracene paste, anthracene fraction	295-275-9	91995-15-2
Anthracene oil, anthracene-low	292-604-8	90640-82-7
Anthracene oil, anthracene paste	292-603-2	90640-81-6
Pitch, coal tar, high temp.	266-028-2	65996-93-2
Acrylamide	201-173-7	79-06-1
Aluminosilicate Refractory Ceramic		
Zirconia Aluminosilicate, Refractory Ceramic Fibres		
2,4-Dinitrotoluene	204-450-0	121-14-2
Diisobutyl phthalate	201-553-2	84-69-5
Lead chromate	231-846-0	7758-97-6
Lead chromate molybdate sulphate red (C.I. Pigment Red 104)	235-759-9	12656-85-8
Lead sulfochromate yellow (C.I. Pigment Yellow 34)	215-693-7	1344-37-2
tris(2-chloroethyl)phosphate	204-118-5	115-96-8

Perfluorooctane sulfonates (PFOS) C8F17SO2X (X = OH, Metal salt (O-M+), halide, amide, and other derivatives including polymers)

Substances meeting the criteria of flammability in Directive 67/548/ EEC and classified as flammable, highly flammable or extremely flammable regardless of whether they appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 or not.

Substances which appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 classified as carcinogen category 1A or 1B (Table 3.1) or carcinogen category 1 or 2 (Table 3.2) and listed as follows:
- — Carcinogen category 1A (Table 3.1)/carcinogen category 1 (Table 3.2) listed in Appendix 1
- — Carcinogen category 1B (Table 3.1)/carcinogen category 2 (Table 3.2) listed in Appendix 2

Substances which appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 classified as germ cell mutagen category 1A or 1B (Table 3.1) or mutagen category 1 or 2 (Table 3.2) and listed as follows:
- — Mutagen category 1A (Table 3.1)/mutagen category 1 (Table 3.2) listed in Appendix 3
- — Mutagen category 1B (Table 3.1)/mutagen category 2 (Table 3.2) listed in Appendix 4

REACH ECHA/PR/09/15 Updates of January 2010 (Continued)

Substances which appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 classified as toxic to reproduction category 1A or 1B (Table 3.1) or toxic to reproduction category 1 or 2 (Table 3.2) and listed as follows:

— Reproductive toxicant category 1A adverse effects on sexual function and fertility or on development (Table 3.1) or reproductive toxicant category 1 with R60 (May impair fertility) or R61 (May cause harm to the unborn child) (Table 3.2) listed in Appendix 5

— Reproductive toxicant category 1B adverse effects on sexual function and fertility or on development (Table 3.1) or reproductive toxicant category 2 with R60 (May impair fertility) or R61 (May cause harm to the unborn child) (Table 3.2) listed in Appendix 6

Substances or mixtures, which are regarded as dangerous according to the definitions in European Union Directives 67/548/EEC and 1999/45/EC.

REACH Updates ED/30/2010 of June 2010 (All product versions are REACH Compliant - No SVHCs present)

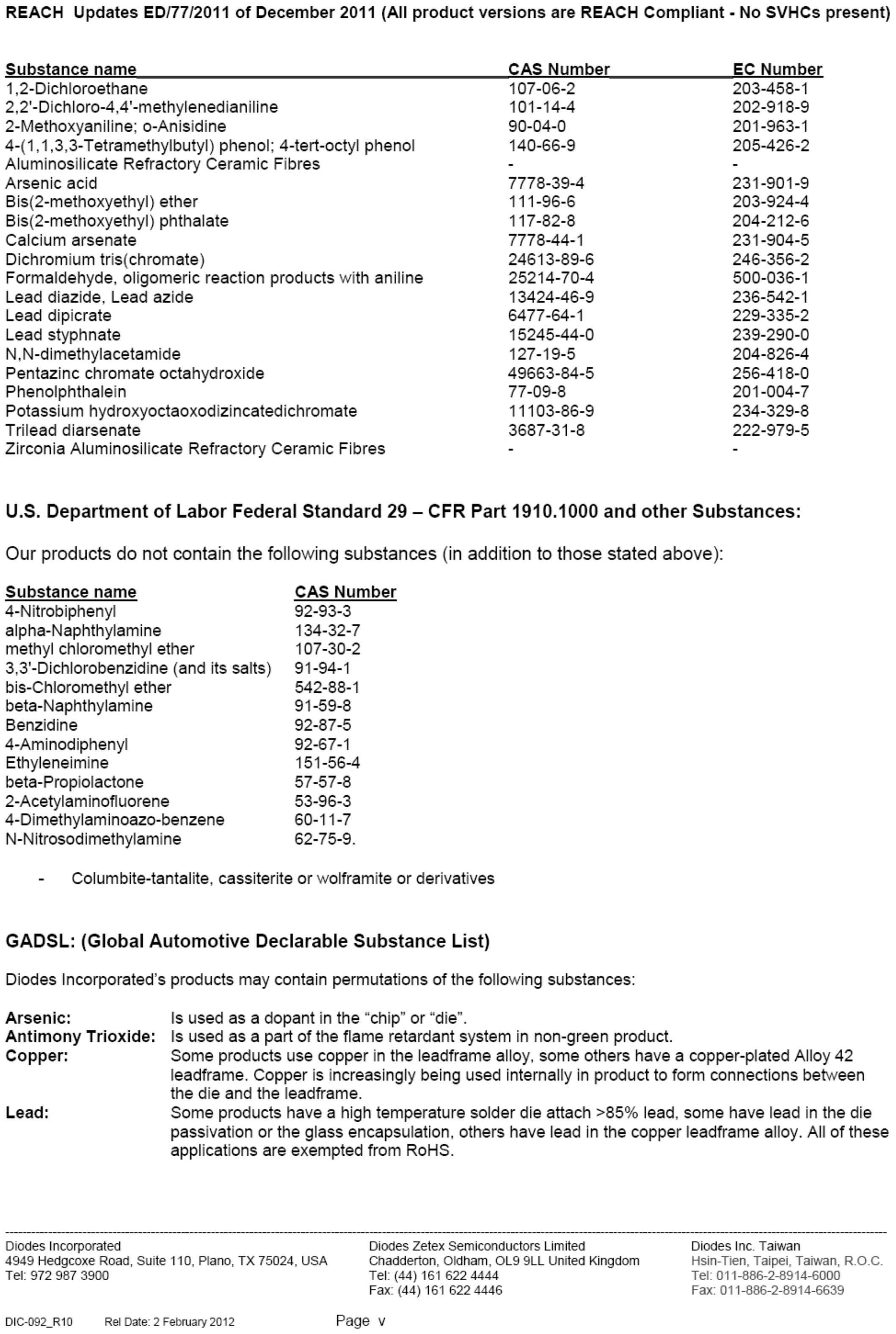
Substance name	CAS Number	EC Number
Trichloroethylene	79-01-6	201-167-4
Boric acid	10043-35-3 11113-50-1	233-139-2 234-343-4
Disodium tetraborate, anhydrous	1303-96-4 1330-43-4 12179-04-3	215-540-4
Tetraboron disodium heptaoxide, hydrate	12267-73-1	235-541-3
Potassium dichromate	7778-50-9	231-906-6
Ammonium dichromate	7789-09-5	232-143-1
Potassium chromate	7789-00-6	232-140-5
Sodium chromate	7775-11-3	231-889-5

REACH Updates ED/95/2010 of December 2010 (All product versions are REACH Compliant - No SVHCs present)

Substance name	CAS Number	EC Number
Cobalt(II) sulphate	10124-43-3	233-334-2
Cobalt(II) dinitrate	10141-05-6	233-402-1
Cobalt(II) carbonate	513-79-1	208-169-4
Cobalt(II) diacetate	71-48-7	200-755-8
2-Methoxyethanol	109-86-4	203-713-7
2-Ethoxyethanol	110-80-5	203-804-1
Chromium trioxide	1333-82-0	215-607-8
Chromic acid, Oligomers of chromic acid and dichromic acid, Dichromic acid	7738-94-5 13530-68-2	231-801-5 236-881-5

REACH Updates ED/31/2011 of June 2011 (All product versions are REACH Compliant - No SVHCs present)

Substance name	CAS Number	EC Number
Cobalt dichloride	7646-79-9	231-589-4
1,2-Benzenedicarboxylic acid, di-C6-8-branched alkyl esters, C7-rich	71888-89-6	276-158-1
1,2,3-Trichloropropane	96-18-4	202-486-1
1-Methyl-2-pyrrolidone	872-50-4	212-828-1
Hydrazine	302-01-2 / 7803-57-8	206-114-9
1,2-Benzenedicarboxylic acid, di-C7-11-branched and linear alkyl esters	68515-42-4	271-084-6
Strontium chromate	7789-06-2	232-142-6
2-Ethoxyethyl acetate	111-15-9	203-839-2



REACH Updates ED/77/2011 of December 2011 (All product versions are REACH Compliant - No SVHCs present)

Substance name	CAS Number	EC Number
1,2-Dichloroethane	107-06-2	203-458-1
2,2'-Dichloro-4,4'-methylenedianiline	101-14-4	202-918-9
2-Methoxyaniline; o-Anisidine	90-04-0	201-963-1
4-(1,1,3,3-Tetramethylbutyl) phenol; 4-tert-octyl phenol	140-66-9	205-426-2
Aluminosilicate Refractory Ceramic Fibres	-	-
Arsenic acid	7778-39-4	231-901-9
Bis(2-methoxyethyl) ether	111-96-6	203-924-4
Bis(2-methoxyethyl) phthalate	117-82-8	204-212-6
Calcium arsenate	7778-44-1	231-904-5
Dichromium tris(chromate)	24613-89-6	246-356-2
Formaldehyde, oligomeric reaction products with aniline	25214-70-4	500-036-1
Lead diazide, Lead azide	13424-46-9	236-542-1
Lead dipicrate	6477-64-1	229-335-2
Lead styphnate	15245-44-0	239-290-0
N,N-dimethylacetamide	127-19-5	204-826-4
Pentazinc chromate octahydroxide	49663-84-5	256-418-0
Phenolphthalein	77-09-8	201-004-7
Potassium hydroxyoctaoxodizincatedichromate	11103-86-9	234-329-8
Trilead diarsenate	3687-31-8	222-979-5
Zirconia Aluminosilicate Refractory Ceramic Fibres	-	-

U.S. Department of Labor Federal Standard 29 – CFR Part 1910.1000 and other Substances:

Our products do not contain the following substances (in addition to those stated above):

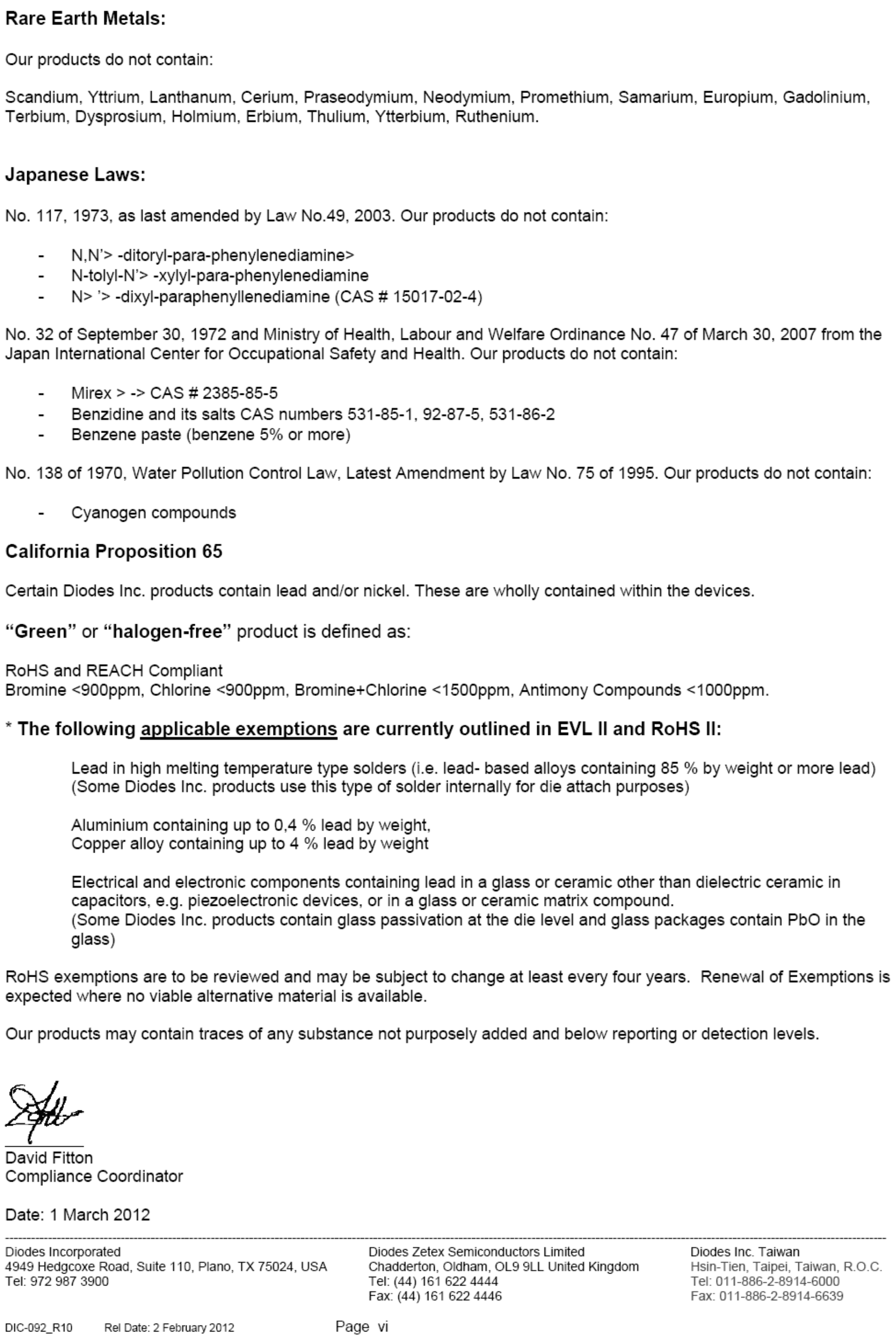
Substance name	CAS Number
4-Nitrobiphenyl	92-93-3
alpha-Naphthylamine	134-32-7
methyl chloromethyl ether	107-30-2
3,3'-Dichlorobenzidine (and its salts)	91-94-1
bis-Chloromethyl ether	542-88-1
beta-Naphthylamine	91-59-8
Benzidine	92-87-5
4-Aminodiphenyl	92-67-1
Ethyleneimine	151-56-4
beta-Propiolactone	57-57-8
2-Acetylaminofluorene	53-96-3
4-Dimethylaminoazo-benzene	60-11-7
N-Nitrosodimethylamine	62-75-9.

- Columbite-tantalite, cassiterite or wolframite or derivatives

GADSL: (Global Automotive Declarable Substance List)

Diodes Incorporated's products may contain permutations of the following substances:

Arsenic:	Is used as a dopant in the "chip" or "die".
Antimony Trioxide:	Is used as a part of the flame retardant system in non-green product.
Copper:	Some products use copper in the leadframe alloy, some others have a copper-plated Alloy 42 leadframe. Copper is increasingly being used internally in product to form connections between the die and the leadframe.
Lead:	Some products have a high temperature solder die attach >85% lead, some have lead in the die passivation or the glass encapsulation, others have lead in the copper leadframe alloy. All of these applications are exempted from RoHS.



Rare Earth Metals:

Our products do not contain:

Scandium, Yttrium, Lanthanum, Cerium, Praseodymium, Neodymium, Promethium, Samarium, Europium, Gadolinium, Terbium, Dysprosium, Holmium, Erbium, Thulium, Ytterbium, Ruthenium.

Japanese Laws:

No. 117, 1973, as last amended by Law No.49, 2003. Our products do not contain:

- N,N'> -ditoryl-para-phenylenediamine>
- N-tolyl-N'> -xylyl-para-phenylenediamine
- N> '> -dixyl-paraphenyllenediamine (CAS # 15017-02-4)

No. 32 of September 30, 1972 and Ministry of Health, Labour and Welfare Ordinance No. 47 of March 30, 2007 from the Japan International Center for Occupational Safety and Health. Our products do not contain:

- Mirex > -> CAS # 2385-85-5
- Benzidine and its salts CAS numbers 531-85-1, 92-87-5, 531-86-2
- Benzene paste (benzene 5% or more)

No. 138 of 1970, Water Pollution Control Law, Latest Amendment by Law No. 75 of 1995. Our products do not contain:

- Cyanogen compounds

California Proposition 65

Certain Diodes Inc. products contain lead and/or nickel. These are wholly contained within the devices.

"Green" or **"halogen-free"** product is defined as:

RoHS and REACH Compliant
Bromine <900ppm, Chlorine <900ppm, Bromine+Chlorine <1500ppm, Antimony Compounds <1000ppm.

* The following applicable exemptions are currently outlined in EVL II and RoHS II:

Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
(Some Diodes Inc. products use this type of solder internally for die attach purposes)

Aluminium containing up to 0,4 % lead by weight,
Copper alloy containing up to 4 % lead by weight

Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
(Some Diodes Inc. products contain glass passivation at the die level and glass packages contain PbO in the glass)

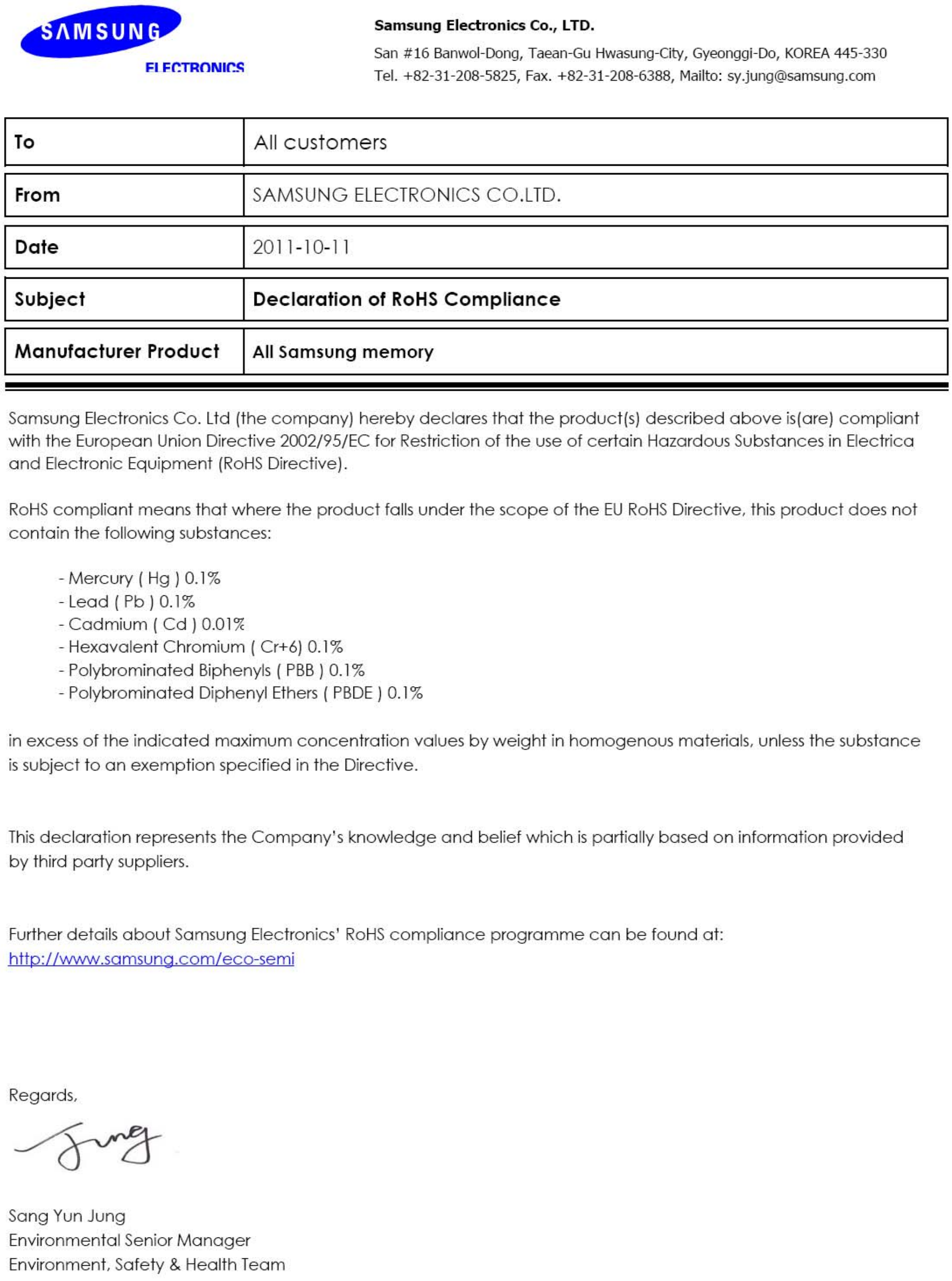
RoHS exemptions are to be reviewed and may be subject to change at least every four years. Renewal of Exemptions is expected where no viable alternative material is available.

Our products may contain traces of any substance not purposely added and below reporting or detection levels.

David Fitton
Compliance Coordinator

Date: 1 March 2012

DECLARATION LETTER FROM SAMSUNG



SAMSUNG
ELECTRONICS

Samsung Electronics Co., LTD.
San #16 Banwol-Dong, Taean-Gu Hwasung-City, Gyeonggi-Do, KOREA 445-330
Tel. +82-31-208-5825, Fax. +82-31-208-6388, Mailto: sy.jung@samsung.com

To	All customers
From	SAMSUNG ELECTRONICS CO.LTD.
Date	2011-10-11
Subject	**Declaration of RoHS Compliance**
Manufacturer Product	**All Samsung memory**

Samsung Electronics Co. Ltd (the company) hereby declares that the product(s) described above is(are) compliant with the European Union Directive 2002/95/EC for Restriction of the use of certain Hazardous Substances in Electrica and Electronic Equipment (RoHS Directive).

RoHS compliant means that where the product falls under the scope of the EU RoHS Directive, this product does not contain the following substances:

- Mercury (Hg) 0.1%
- Lead (Pb) 0.1%
- Cadmium (Cd) 0.01%
- Hexavalent Chromium (Cr+6) 0.1%
- Polybrominated Biphenyls (PBB) 0.1%
- Polybrominated Diphenyl Ethers (PBDE) 0.1%

in excess of the indicated maximum concentration values by weight in homogenous materials, unless the substance is subject to an exemption specified in the Directive.

This declaration represents the Company's knowledge and belief which is partially based on information provided by third party suppliers.

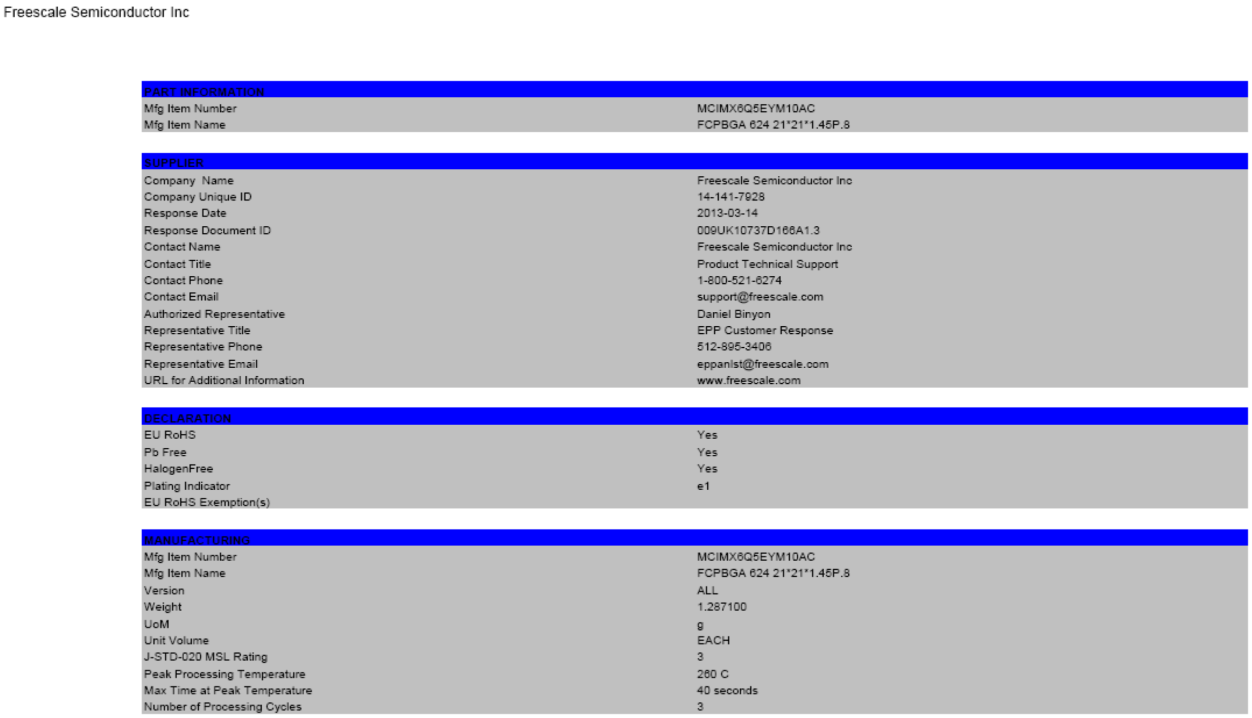
Further details about Samsung Electronics' RoHS compliance programme can be found at:
http://www.samsung.com/eco-semi

Regards,

Jung

Sang Yun Jung
Environmental Senior Manager
Environment, Safety & Health Team

DECLARATION LETTER FROM FREESCALE



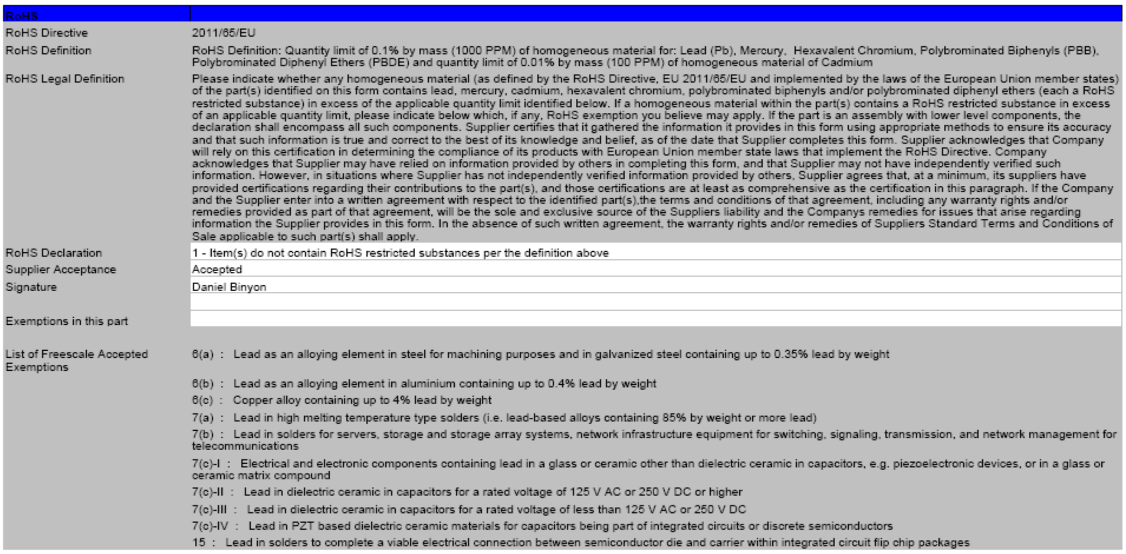
Freescale Semiconductor Inc

PART INFORMATION	
Mfg Item Number	MCIMX6Q5EYM10AC
Mfg Item Name	FCPBGA 624 21*21*1.45P.8

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2013-03-14
Response Document ID	009UK10737D166A1.3
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

MANUFACTURING	
Mfg Item Number	MCIMX6Q5EYM10AC
Mfg Item Name	FCPBGA 624 21*21*1.45P.8
Version	ALL
Weight	1.287100
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3



RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

DECLARATION LETTER FROM TOREX

Torex...Powerfully Small!

TOREX Semiconductor Ltd.
Sakura Nihonbashi Bldg. 8F
1-13-12, Nihonbashi, Kayabacho
Chuo-Ku, Tokyo 103-0025
Japan
Phone: +81-3-5652-8725
Fax: +81-3-5652-8731
http://www.torex.co.jp

Certificate of EU RoHS Compliance

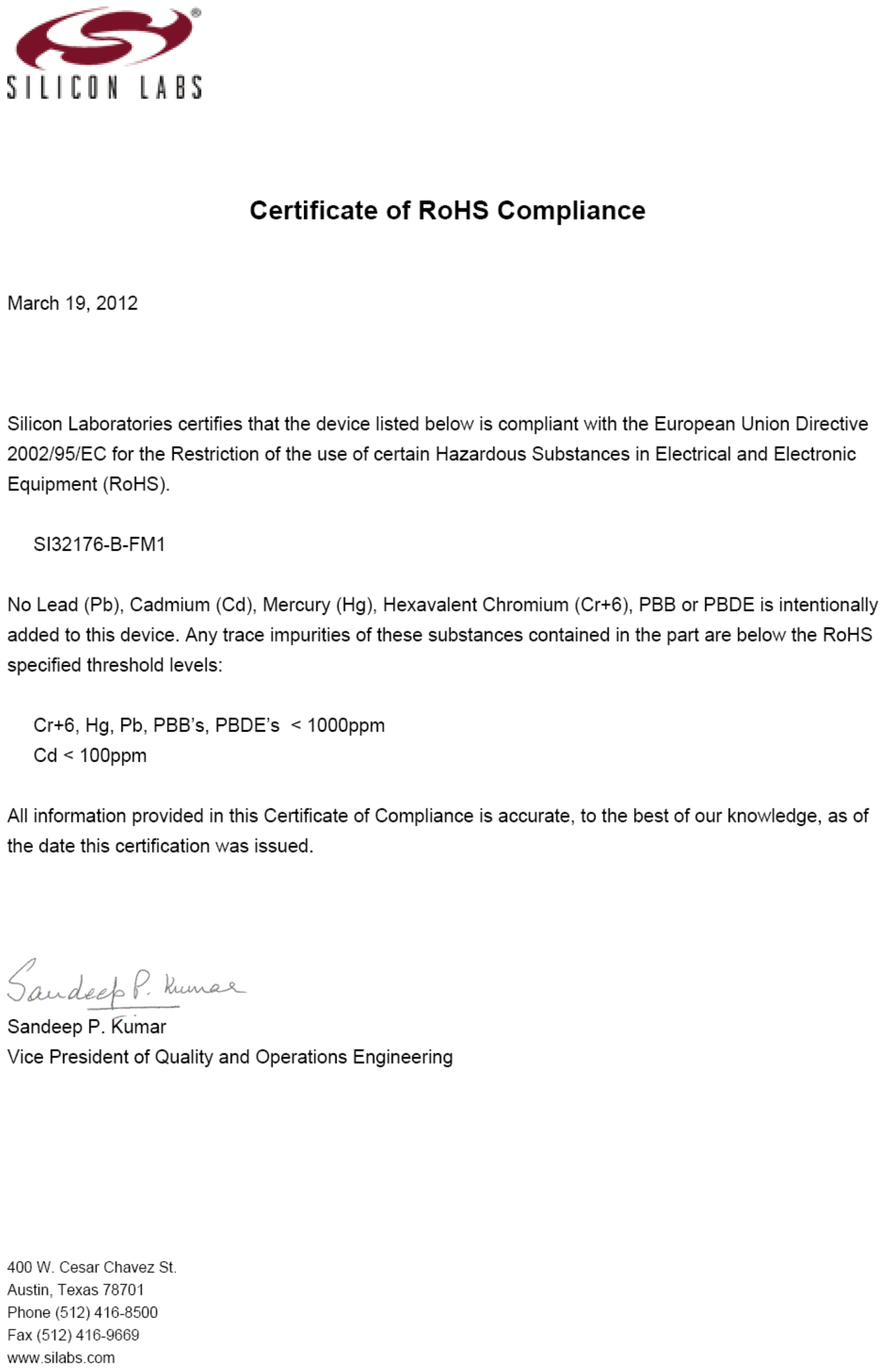
We hereby assure that all products from TOREX do not intentionally contain any of the RoHS-referred substances listed below (except for exempted applications by the directive).

- ✧ Cadmium
- ✧ Lead
- ✧ Mercury
- ✧ Hexavalent chromium
- ✧ PBB
- ✧ PBDE

For any inquiries regarding this issue, please contact our sales dept.

Takara Yoshida
Director, Quality Assurance Dept.

DECLARATION LETTER SILICONLABS



SILICON LABS

Certificate of RoHS Compliance

March 19, 2012

Silicon Laboratories certifies that the device listed below is compliant with the European Union Directive 2002/95/EC for the Restriction of the use of certain Hazardous Substances in Electrical and Electronic Equipment (RoHS).

SI32176-B-FM1

No Lead (Pb), Cadmium (Cd), Mercury (Hg), Hexavalent Chromium (Cr+6), PBB or PBDE is intentionally added to this device. Any trace impurities of these substances contained in the part are below the RoHS specified threshold levels:

Cr+6, Hg, Pb, PBB's, PBDE's < 1000ppm
Cd < 100ppm

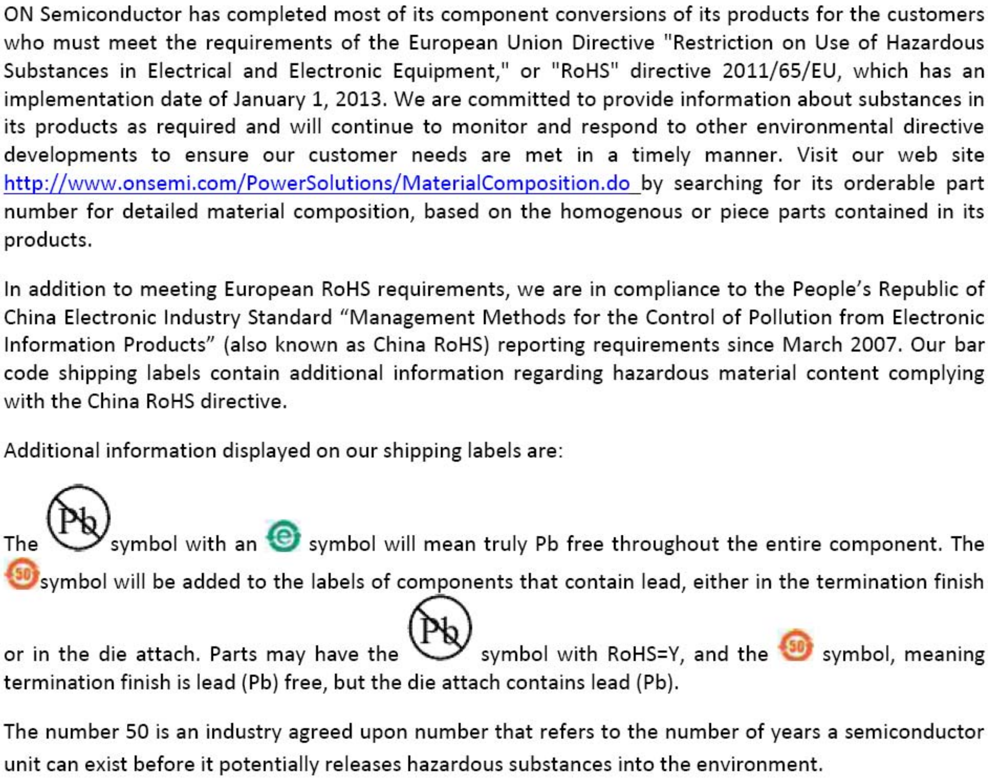
All information provided in this Certificate of Compliance is accurate, to the best of our knowledge, as of the date this certification was issued.

Sandeep P. Kumar

Sandeep P. Kumar
Vice President of Quality and Operations Engineering

400 W. Cesar Chavez St.
Austin, Texas 78701
Phone (512) 416-8500
Fax (512) 416-9669
www.silabs.com

DECLARATION LETTER FROM ON SEMICONDUCTOR



ON Semiconductor has completed most of its component conversions of its products for the customers who must meet the requirements of the European Union Directive "Restriction on Use of Hazardous Substances in Electrical and Electronic Equipment," or "RoHS" directive 2011/65/EU, which has an implementation date of January 1, 2013. We are committed to provide information about substances in its products as required and will continue to monitor and respond to other environmental directive developments to ensure our customer needs are met in a timely manner. Visit our web site http://www.onsemi.com/PowerSolutions/MaterialComposition.do by searching for its orderable part number for detailed material composition, based on the homogenous or piece parts contained in its products.

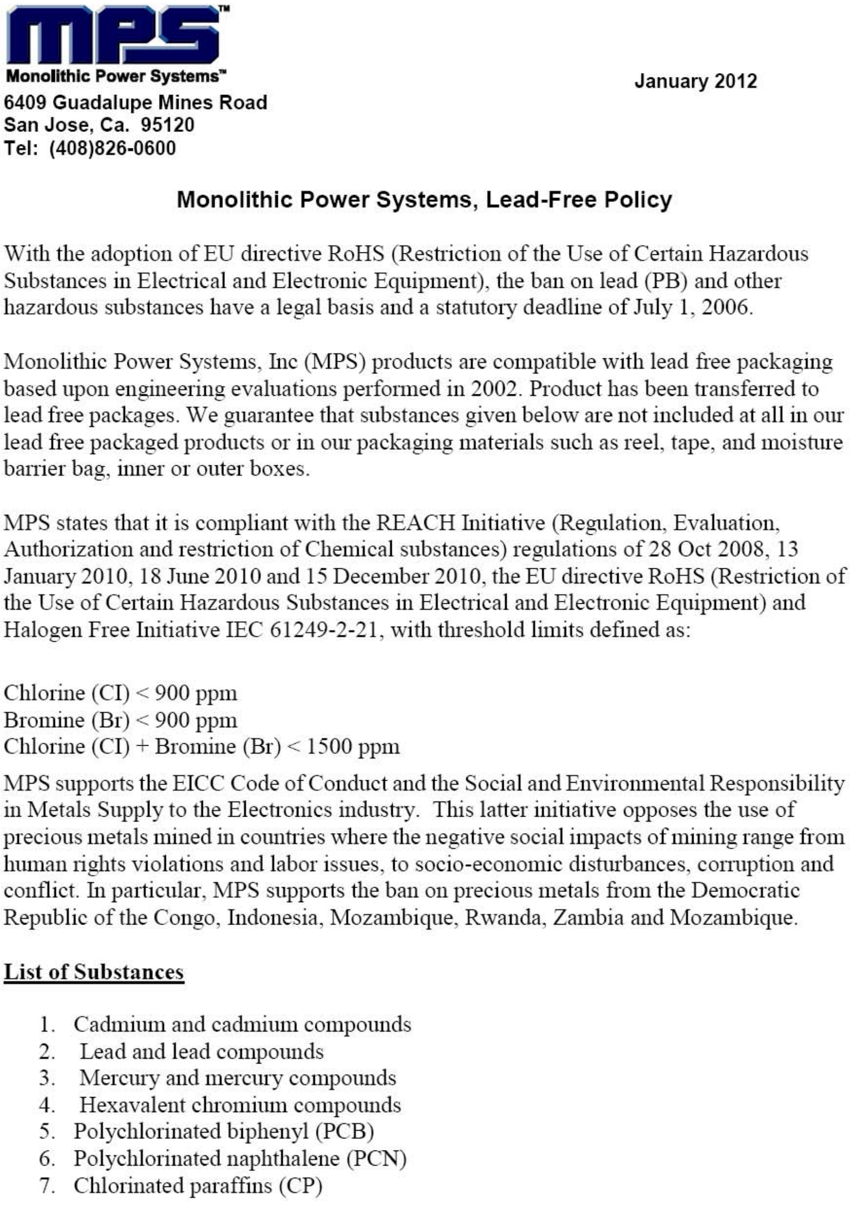
In addition to meeting European RoHS requirements, we are in compliance to the People's Republic of China Electronic Industry Standard "Management Methods for the Control of Pollution from Electronic Information Products" (also known as China RoHS) reporting requirements since March 2007. Our bar code shipping labels contain additional information regarding hazardous material content complying with the China RoHS directive.

Additional information displayed on our shipping labels are:

The Pb symbol with an e symbol will mean truly Pb free throughout the entire component. The 50 symbol will be added to the labels of components that contain lead, either in the termination finish or in the die attach. Parts may have the Pb symbol with RoHS=Y, and the 50 symbol, meaning termination finish is lead (Pb) free, but the die attach contains lead (Pb).

The number 50 is an industry agreed upon number that refers to the number of years a semiconductor unit can exist before it potentially releases hazardous substances into the environment.

DECLARATION LETTER FROM MPS



Monolithic Power Systems™
6409 Guadalupe Mines Road
San Jose, Ca. 95120
Tel: (408)826-0600

January 2012

Monolithic Power Systems, Lead-Free Policy

With the adoption of EU directive RoHS (Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), the ban on lead (PB) and other hazardous substances have a legal basis and a statutory deadline of July 1, 2006.

Monolithic Power Systems, Inc (MPS) products are compatible with lead free packaging based upon engineering evaluations performed in 2002. Product has been transferred to lead free packages. We guarantee that substances given below are not included at all in our lead free packaged products or in our packaging materials such as reel, tape, and moisture barrier bag, inner or outer boxes.

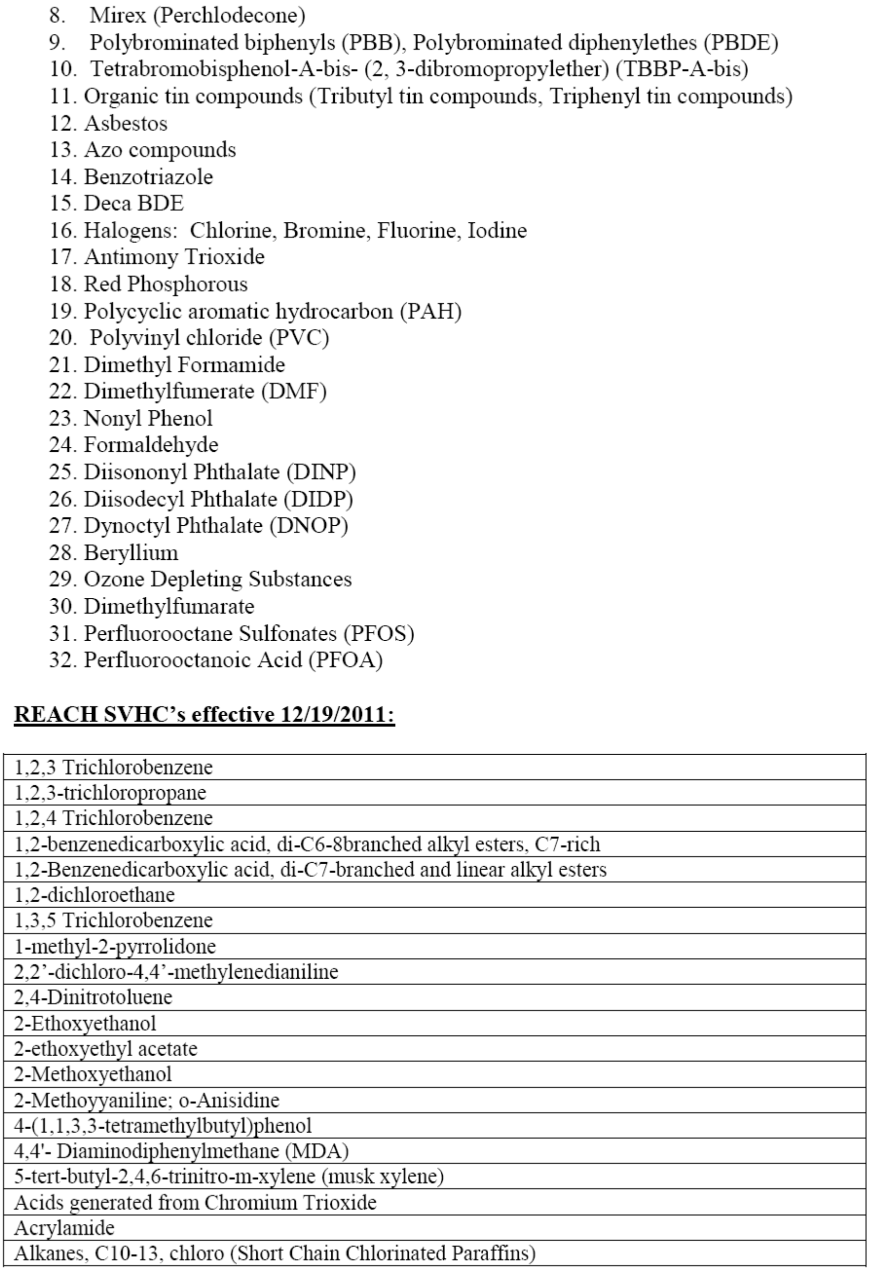
MPS states that it is compliant with the REACH Initiative (Regulation, Evaluation, Authorization and restriction of Chemical substances) regulations of 28 Oct 2008, 13 January 2010, 18 June 2010 and 15 December 2010, the EU directive RoHS (Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) and Halogen Free Initiative IEC 61249-2-21, with threshold limits defined as:

Chlorine (CI) < 900 ppm
Bromine (Br) < 900 ppm
Chlorine (CI) + Bromine (Br) < 1500 ppm

MPS supports the EICC Code of Conduct and the Social and Environmental Responsibility in Metals Supply to the Electronics industry. This latter initiative opposes the use of precious metals mined in countries where the negative social impacts of mining range from human rights violations and labor issues, to socio-economic disturbances, corruption and conflict. In particular, MPS supports the ban on precious metals from the Democratic Republic of the Congo, Indonesia, Mozambique, Rwanda, Zambia and Mozambique.

List of Substances

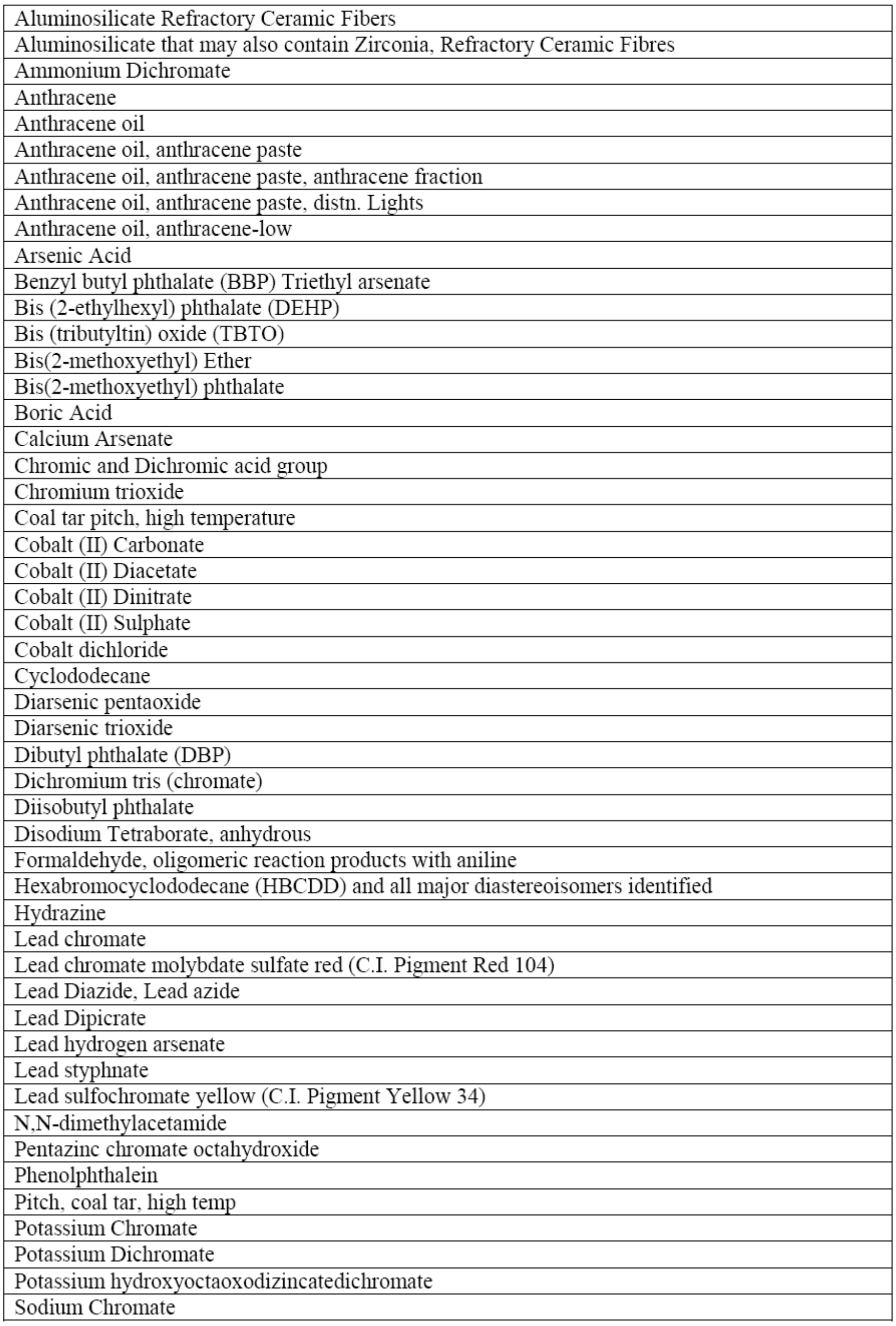
1. Cadmium and cadmium compounds
2. Lead and lead compounds
3. Mercury and mercury compounds
4. Hexavalent chromium compounds
5. Polychlorinated biphenyl (PCB)
6. Polychlorinated naphthalene (PCN)
7. Chlorinated paraffins (CP)



8. Mirex (Perchlodecone)
9. Polybrominated biphenyls (PBB), Polybrominated diphenylethes (PBDE)
10. Tetrabromobisphenol-A-bis- (2, 3-dibromopropylether) (TBBP-A-bis)
11. Organic tin compounds (Tributyl tin compounds, Triphenyl tin compounds)
12. Asbestos
13. Azo compounds
14. Benzotriazole
15. Deca BDE
16. Halogens: Chlorine, Bromine, Fluorine, Iodine
17. Antimony Trioxide
18. Red Phosphorous
19. Polycyclic aromatic hydrocarbon (PAH)
20. Polyvinyl chloride (PVC)
21. Dimethyl Formamide
22. Dimethylfumerate (DMF)
23. Nonyl Phenol
24. Formaldehyde
25. Diisononyl Phthalate (DINP)
26. Diisodecyl Phthalate (DIDP)
27. Dynoctyl Phthalate (DNOP)
28. Beryllium
29. Ozone Depleting Substances
30. Dimethylfumarate
31. Perfluorooctane Sulfonates (PFOS)
32. Perfluorooctanoic Acid (PFOA)

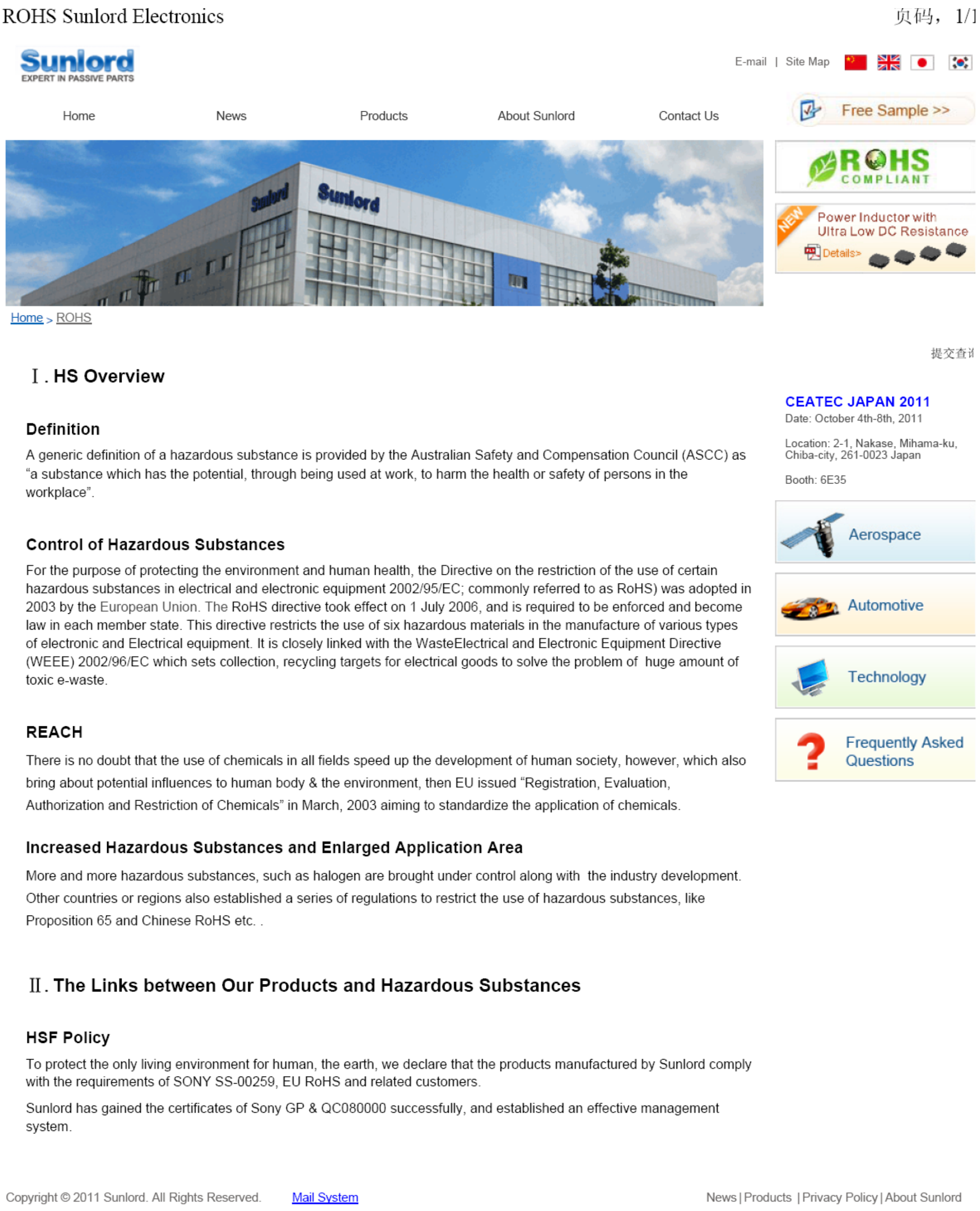
REACH SVHC's effective 12/19/2011:

1,2,3 Trichlorobenzene
1,2,3-trichloropropane
1,2,4 Trichlorobenzene
1,2-benzenedicarboxylic acid, di-C6-8branched alkyl esters, C7-rich
1,2-Benzenedicarboxylic acid, di-C7-branched and linear alkyl esters
1,2-dichloroethane
1,3,5 Trichlorobenzene
1-methyl-2-pyrrolidone
2,2'-dichloro-4,4'-methylenedianiline
2,4-Dinitrotoluene
2-Ethoxyethanol
2-ethoxyethyl acetate
2-Methoxyethanol
2-Methoyyaniline; o-Anisidine
4-(1,1,3,3-tetramethylbutyl)phenol
4,4'- Diaminodiphenylmethane (MDA)
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Acids generated from Chromium Trioxide
Acrylamide
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)



Aluminosilicate Refractory Ceramic Fibers
Aluminosilicate that may also contain Zirconia, Refractory Ceramic Fibres
Ammonium Dichromate
Anthracene
Anthracene oil
Anthracene oil, anthracene paste
Anthracene oil, anthracene paste, anthracene fraction
Anthracene oil, anthracene paste, distn. Lights
Anthracene oil, anthracene-low
Arsenic Acid
Benzyl butyl phthalate (BBP) Triethyl arsenate
Bis (2-ethylhexyl) phthalate (DEHP)
Bis (tributyltin) oxide (TBTO)
Bis(2-methoxyethyl) Ether
Bis(2-methoxyethyl) phthalate
Boric Acid
Calcium Arsenate
Chromic and Dichromic acid group
Chromium trioxide
Coal tar pitch, high temperature
Cobalt (II) Carbonate
Cobalt (II) Diacetate
Cobalt (II) Dinitrate
Cobalt (II) Sulphate
Cobalt dichloride
Cyclododecane
Diarsenic pentaoxide
Diarsenic trioxide
Dibutyl phthalate (DBP)
Dichromium tris (chromate)
Diisobutyl phthalate
Disodium Tetraborate, anhydrous
Formaldehyde, oligomeric reaction products with aniline
Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified
Hydrazine
Lead chromate
Lead chromate molybdate sulfate red (C.I. Pigment Red 104)
Lead Diazide, Lead azide
Lead Dipicrate
Lead hydrogen arsenate
Lead styphnate
Lead sulfochromate yellow (C.I. Pigment Yellow 34)
N,N-dimethylacetamide
Pentazinc chromate octahydroxide
Phenolphthalein
Pitch, coal tar, high temp
Potassium Chromate
Potassium Dichromate
Potassium hydroxyoctaoxodizincatedichromate
Sodium Chromate

DECLARATION LETTER FROM SUNLORD



ROHS Sunlord Electronics 页码，1/1

Sunlord
EXPERT IN PASSIVE PARTS

E-mail | Site Map

Home News Products About Sunlord Contact Us

Free Sample >>

ROHS COMPLIANT

NEW Power Inductor with Ultra Low DC Resistance Details>

Home > ROHS

提交查

Ⅰ. HS Overview

Definition

A generic definition of a hazardous substance is provided by the Australian Safety and Compensation Council (ASCC) as "a substance which has the potential, through being used at work, to harm the health or safety of persons in the workplace".

Control of Hazardous Substances

For the purpose of protecting the environment and human health, the Directive on the restriction of the use of certain hazardous substances in electrical and electronic equipment 2002/95/EC; commonly referred to as RoHS) was adopted in 2003 by the European Union. The RoHS directive took effect on 1 July 2006, and is required to be enforced and become law in each member state. This directive restricts the use of six hazardous materials in the manufacture of various types of electronic and Electrical equipment. It is closely linked with the WasteElectrical and Electronic Equipment Directive (WEEE) 2002/96/EC which sets collection, recycling targets for electrical goods to solve the problem of huge amount of toxic e-waste.

REACH

There is no doubt that the use of chemicals in all fields speed up the development of human society, however, which also bring about potential influences to human body & the environment, then EU issued "Registration, Evaluation, Authorization and Restriction of Chemicals" in March, 2003 aiming to standardize the application of chemicals.

Increased Hazardous Substances and Enlarged Application Area

More and more hazardous substances, such as halogen are brought under control along with the industry development. Other countries or regions also established a series of regulations to restrict the use of hazardous substances, like Proposition 65 and Chinese RoHS etc. .

Ⅱ. The Links between Our Products and Hazardous Substances

HSF Policy

To protect the only living environment for human, the earth, we declare that the products manufactured by Sunlord comply with the requirements of SONY SS-00259, EU RoHS and related customers.

Sunlord has gained the certificates of Sony GP & QC080000 successfully, and established an effective management system.

CEATEC JAPAN 2011
Date: October 4th-8th, 2011

Location: 2-1, Nakase, Mihama-ku, Chiba-city, 261-0023 Japan

Booth: 6E35

Aerospace

Automotive

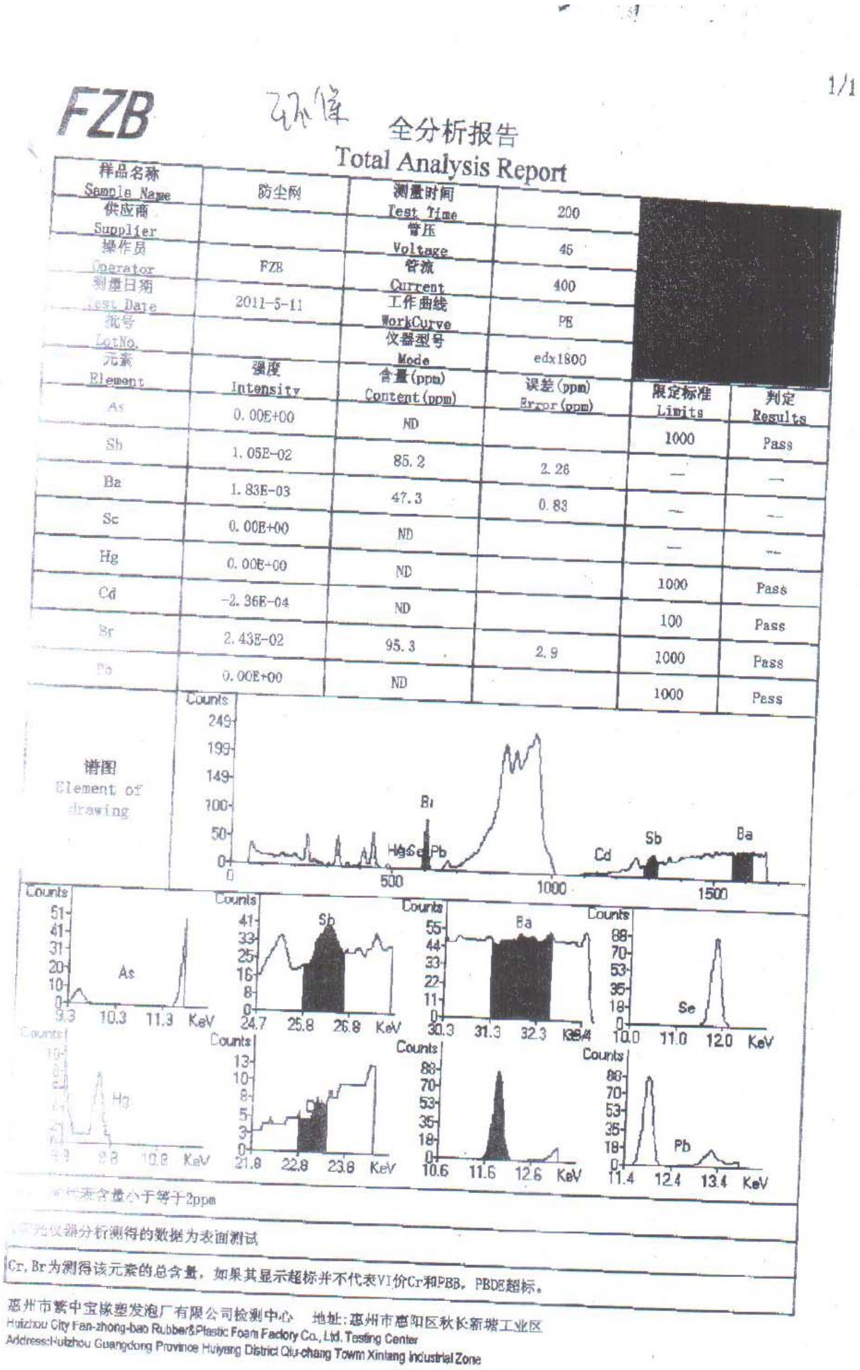
Technology

Frequently Asked Questions

Copyright © 2011 Sunlord. All Rights Reserved. Mail System

News | Products | Privacy Policy | About Sunlord

DECLARATION LETTER FROM FZB



1/1

FZB 环保

全分析报告
Total Analysis Report

样品名称 Sample Name	防尘网	测量时间 Test Time	200
供应商 Supplier		管压 Voltage	45
操作员 Operator	FZB	管流 Current	400
测量日期 Test Date	2011-5-11	工作曲线 WorkCurve	PE
批号 LotNo.		仪器型号 Mode	edx1800

[redacted]

元素 Element	强度 Intensity	含量(ppm) Content(ppm)	误差(ppm) Error(ppm)	限定标准 Limits	判定 Results
As	0.00E+00	ND		1000	Pass
Sb	1.05E-02	85.2	2.26	—	—
Ba	1.83E-03	47.3	0.83	—	—
Se	0.00E+00	ND		—	—
Hg	0.00E+00	ND		1000	Pass
Cd	-2.36E-04	ND		100	Pass
Br	2.43E-02	95.3	2.9	1000	Pass
Pb	0.00E+00	ND		1000	Pass

谱图 Element of drawing

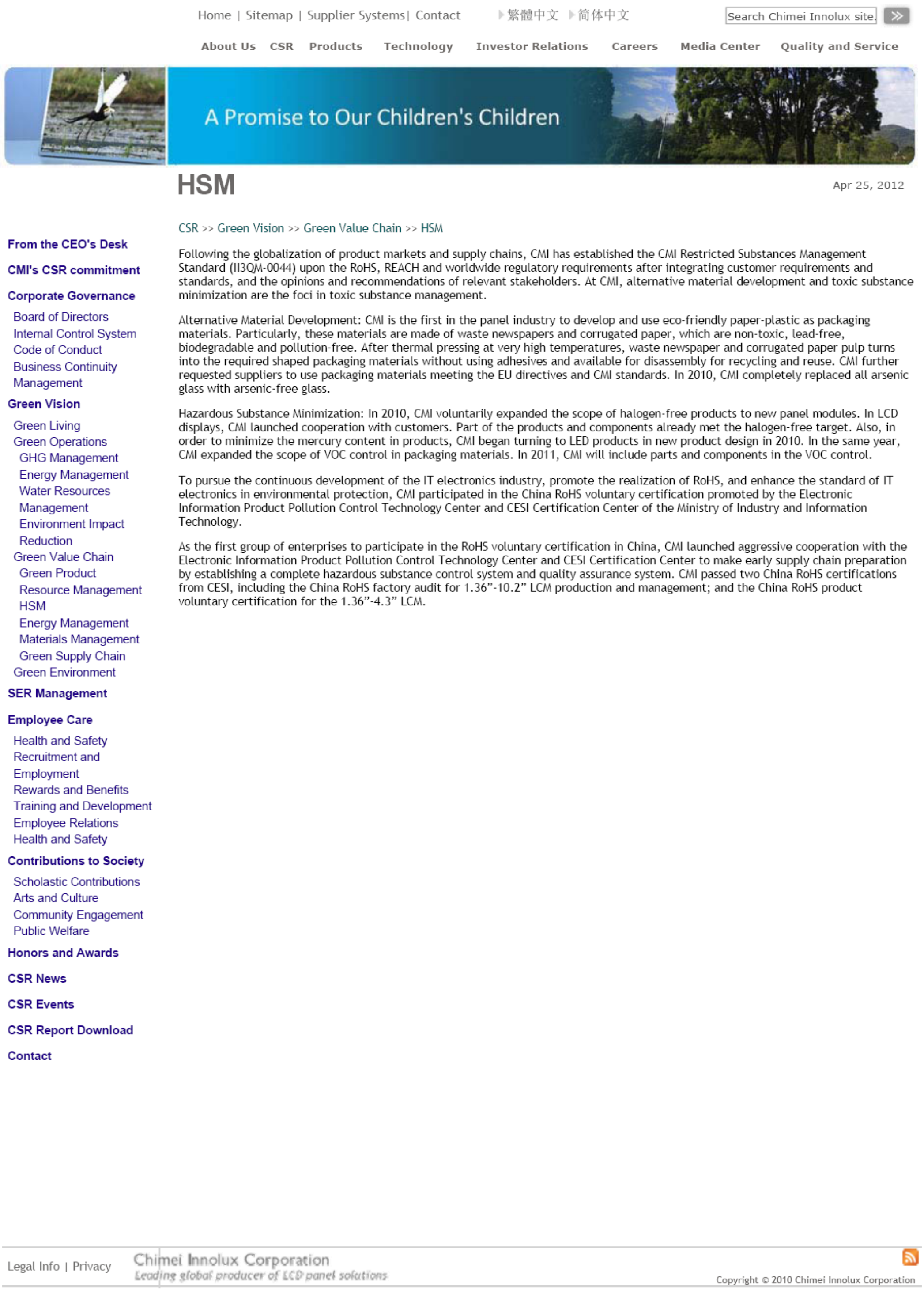
代表含量小于等于2ppm

荧光仪器分析测得的数据为表面测试

Cr, Br为测得该元素的总含量，如果其显示超标并不代表VI价Cr和PBB，PBDE超标。

惠州市繁中宝橡塑发泡厂有限公司检测中心 地址:惠州市惠阳区秋长新塘工业区
Huizhou City Fan-zhong-bao Rubber&Plastic Foam Factory Co., Ltd. Testing Center
Address:Huizhou Guangdong Province Huiyang District Qiu-chang Town Xintang Industrial Zone

DECLARATION LETTER FROM INNOLUX



HSM

Apr 25, 2012

CSR >> Green Vision >> Green Value Chain >> HSM

Following the globalization of product markets and supply chains, CMI has established the CMI Restricted Substances Management Standard (II3QM-0044) upon the RoHS, REACH and worldwide regulatory requirements after integrating customer requirements and standards, and the opinions and recommendations of relevant stakeholders. At CMI, alternative material development and toxic substance minimization are the foci in toxic substance management.

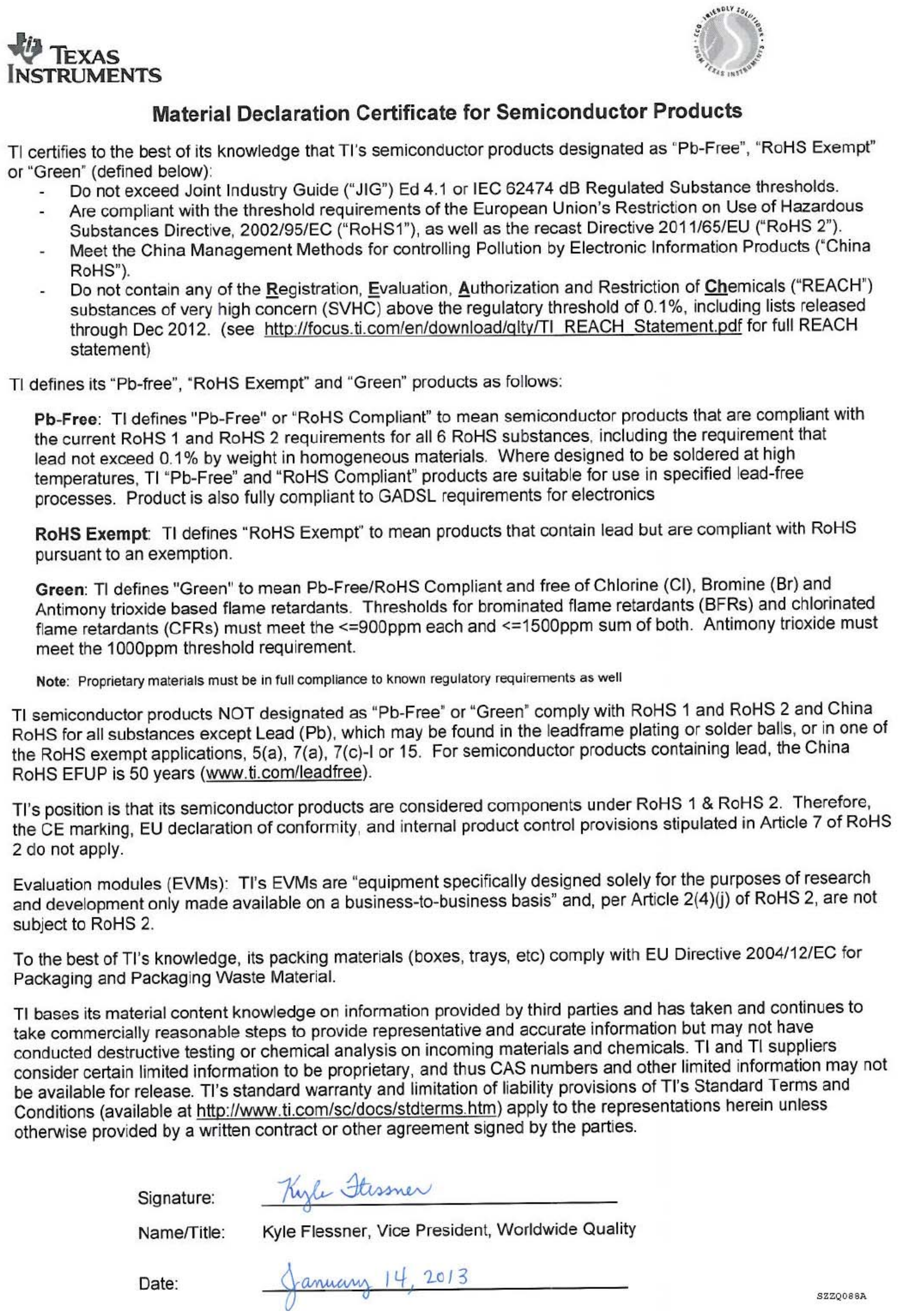
Alternative Material Development: CMI is the first in the panel industry to develop and use eco-friendly paper-plastic as packaging materials. Particularly, these materials are made of waste newspapers and corrugated paper, which are non-toxic, lead-free, biodegradable and pollution-free. After thermal pressing at very high temperatures, waste newspaper and corrugated paper pulp turns into the required shaped packaging materials without using adhesives and available for disassembly for recycling and reuse. CMI further requested suppliers to use packaging materials meeting the EU directives and CMI standards. In 2010, CMI completely replaced all arsenic glass with arsenic-free glass.

Hazardous Substance Minimization: In 2010, CMI voluntarily expanded the scope of halogen-free products to new panel modules. In LCD displays, CMI launched cooperation with customers. Part of the products and components already met the halogen-free target. Also, in order to minimize the mercury content in products, CMI began turning to LED products in new product design in 2010. In the same year, CMI expanded the scope of VOC control in packaging materials. In 2011, CMI will include parts and components in the VOC control.

To pursue the continuous development of the IT electronics industry, promote the realization of RoHS, and enhance the standard of IT electronics in environmental protection, CMI participated in the China RoHS voluntary certification promoted by the Electronic Information Product Pollution Control Technology Center and CESI Certification Center of the Ministry of Industry and Information Technology.

As the first group of enterprises to participate in the RoHS voluntary certification in China, CMI launched aggressive cooperation with the Electronic Information Product Pollution Control Technology Center and CESI Certification Center to make early supply chain preparation by establishing a complete hazardous substance control system and quality assurance system. CMI passed two China RoHS certifications from CESI, including the China RoHS factory audit for 1.36”-10.2” LCM production and management; and the China RoHS product voluntary certification for the 1.36”-4.3” LCM.

DECLARATION LETTER FROM TI



TEXAS INSTRUMENTS

Material Declaration Certificate for Semiconductor Products

TI certifies to the best of its knowledge that TI's semiconductor products designated as "Pb-Free", "RoHS Exempt" or "Green" (defined below):

- Do not exceed Joint Industry Guide ("JIG") Ed 4.1 or IEC 62474 dB Regulated Substance thresholds.
- Are compliant with the threshold requirements of the European Union's Restriction on Use of Hazardous Substances Directive, 2002/95/EC ("RoHS1"), as well as the recast Directive 2011/65/EU ("RoHS 2").
- Meet the China Management Methods for controlling Pollution by Electronic Information Products ("China RoHS").
- Do not contain any of the Registration, Evaluation, Authorization and Restriction of Chemicals ("REACH") substances of very high concern (SVHC) above the regulatory threshold of 0.1%, including lists released through Dec 2012. (see http://focus.ti.com/en/download/qlty/TI_REACH_Statement.pdf for full REACH statement)

TI defines its "Pb-free", "RoHS Exempt" and "Green" products as follows:

Pb-Free: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS 1 and RoHS 2 requirements for all 6 RoHS substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes. Product is also fully compliant to GADSL requirements for electronics

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with RoHS pursuant to an exemption.

Green: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Chlorine (Cl), Bromine (Br) and Antimony trioxide based flame retardants. Thresholds for brominated flame retardants (BFRs) and chlorinated flame retardants (CFRs) must meet the <=900ppm each and <=1500ppm sum of both. Antimony trioxide must meet the 1000ppm threshold requirement.

Note: Proprietary materials must be in full compliance to known regulatory requirements as well

TI semiconductor products NOT designated as "Pb-Free" or "Green" comply with RoHS 1 and RoHS 2 and China RoHS for all substances except Lead (Pb), which may be found in the leadframe plating or solder balls, or in one of the RoHS exempt applications, 5(a), 7(a), 7(c)-I or 15. For semiconductor products containing lead, the China RoHS EFUP is 50 years (www.ti.com/leadfree).

TI's position is that its semiconductor products are considered components under RoHS 1 & RoHS 2. Therefore, the CE marking, EU declaration of conformity, and internal product control provisions stipulated in Article 7 of RoHS 2 do not apply.

Evaluation modules (EVMs): TI's EVMs are "equipment specifically designed solely for the purposes of research and development only made available on a business-to-business basis" and, per Article 2(4)(j) of RoHS 2, are not subject to RoHS 2.

To the best of TI's knowledge, its packing materials (boxes, trays, etc) comply with EU Directive 2004/12/EC for Packaging and Packaging Waste Material.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at http://www.ti.com/sc/docs/stdterms.htm) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

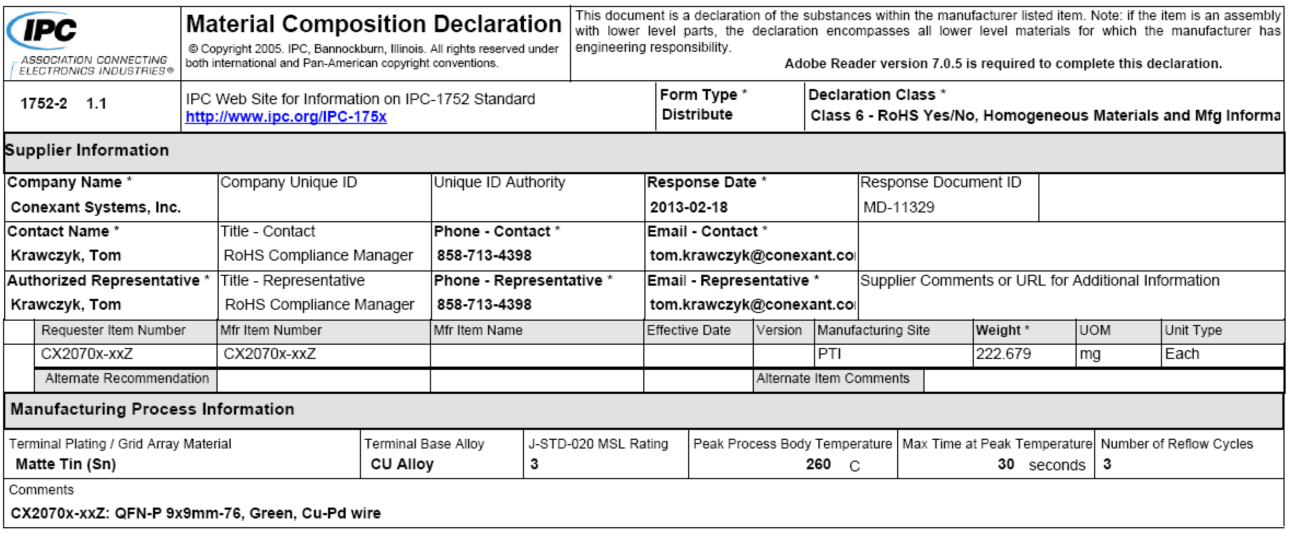
Signature: Kyle Flessner

Name/Title: Kyle Flessner, Vice President, Worldwide Quality

Date: January 14, 2013

SZZQ088A

DECLARATION LETTER FROM IPC



IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	**Form Type** * **Distribute**	**Declaration Class** * **Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa**

Supplier Information

Company Name * **Conexant Systems, Inc.**	Company Unique ID	Unique ID Authority	**Response Date** * **2013-02-18**	Response Document ID MD-11329
Contact Name * **Krawczyk, Tom**	Title - Contact RoHS Compliance Manager	**Phone - Contact** * **858-713-4398**	**Email - Contact** * **tom.krawczyk@conexant.co**	
Authorized Representative * **Krawczyk, Tom**	Title - Representative RoHS Compliance Manager	**Phone - Representative** * **858-713-4398**	**Email - Representative** * **tom.krawczyk@conexant.co**	Supplier Comments or URL for Additional Information

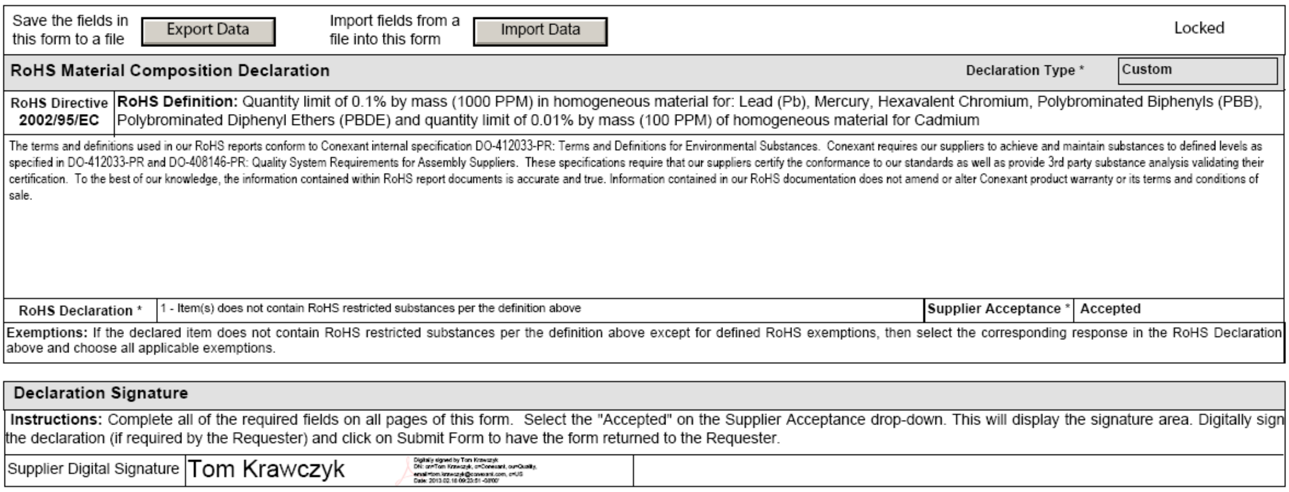
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight** *	UOM	Unit Type
CX2070x-xxZ	CX2070x-xxZ				PTI	222.679	mg	Each
Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Matte Tin (Sn)	**CU Alloy**	**3**	**260** C	**30** seconds	**3**

Comments

CX2070x-xxZ: QFN-P 9x9mm-76, Green, Cu-Pd wire



RoHS Material Composition Declaration — Declaration Type *: Custom

RoHS Directive **2002/95/EC**	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

The terms and definitions used in our RoHS reports conform to Conexant internal specification DO-412033-PR: Terms and Definitions for Environmental Substances. Conexant requires our suppliers to achieve and maintain substances to defined levels as specified in DO-412033-PR and DO-408146-PR: Quality System Requirements for Assembly Suppliers. These specifications require that our suppliers certify the conformance to our standards as well as provide 3rd party substance analysis validating their certification. To the best of our knowledge, the information contained within RoHS report documents is accurate and true. Information contained in our RoHS documentation does not amend or alter Conexant product warranty or its terms and conditions of sale.

RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	**Supplier Acceptance** *	**Accepted**

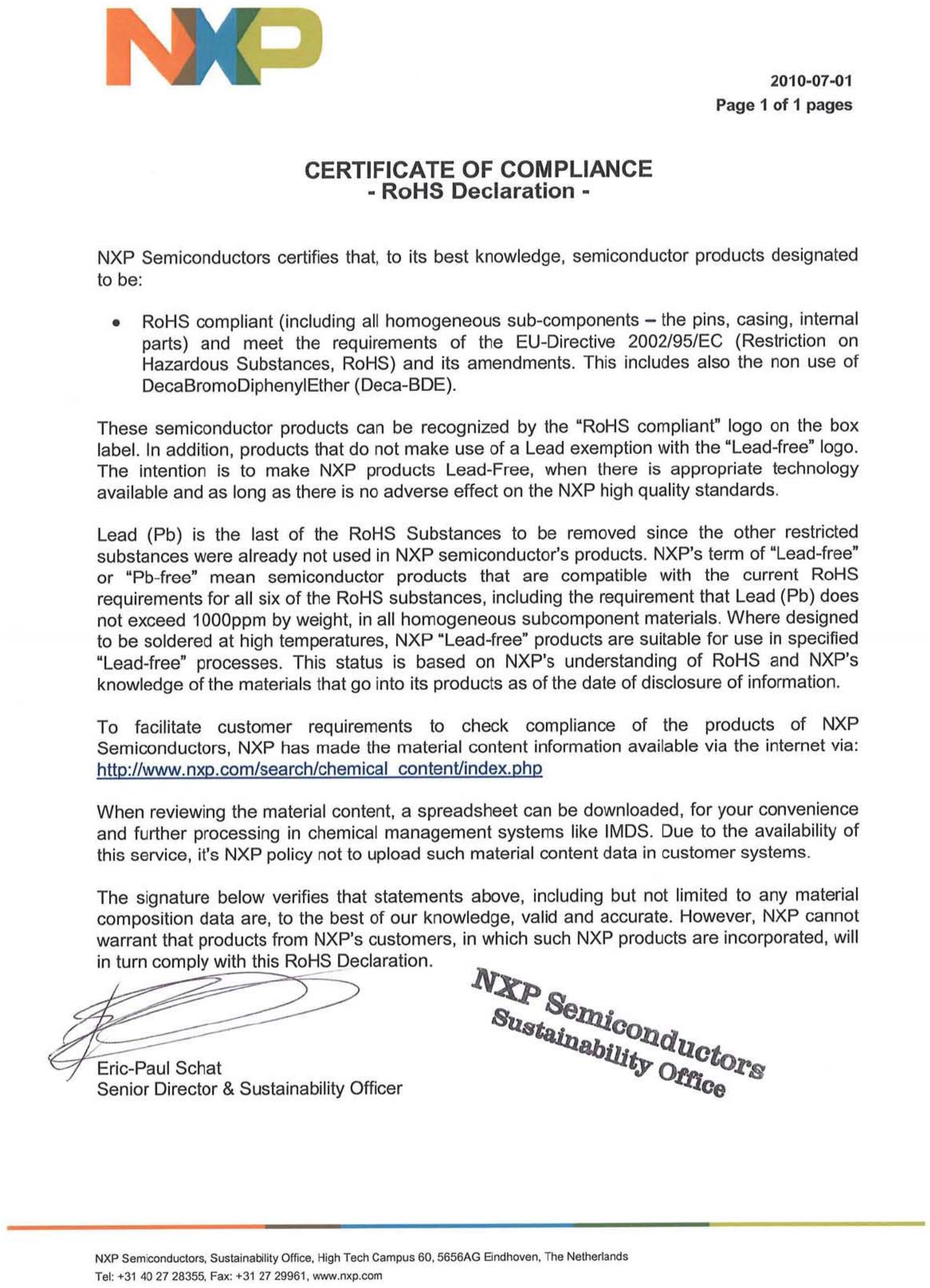
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	Tom Krawczyk Digitally signed by Tom Krawczyk DN: cn=Tom Krawczyk, o=Conexant, ou=Quality, email=tom.krawczyk@conexant.com, c=US Date: 2013.02.18 09:23:51 -08'00'	

DECLARATION LETTER FROM NXP



2010-07-01
Page 1 of 1 pages

CERTIFICATE OF COMPLIANCE
- RoHS Declaration -

NXP Semiconductors certifies that, to its best knowledge, semiconductor products designated to be:

- RoHS compliant (including all homogeneous sub-components – the pins, casing, internal parts) and meet the requirements of the EU-Directive 2002/95/EC (Restriction on Hazardous Substances, RoHS) and its amendments. This includes also the non use of DecaBromoDiphenylEther (Deca-BDE).

These semiconductor products can be recognized by the "RoHS compliant" logo on the box label. In addition, products that do not make use of a Lead exemption with the "Lead-free" logo. The intention is to make NXP products Lead-Free, when there is appropriate technology available and as long as there is no adverse effect on the NXP high quality standards.

Lead (Pb) is the last of the RoHS Substances to be removed since the other restricted substances were already not used in NXP semiconductor's products. NXP's term of "Lead-free" or "Pb-free" mean semiconductor products that are compatible with the current RoHS requirements for all six of the RoHS substances, including the requirement that Lead (Pb) does not exceed 1000ppm by weight, in all homogeneous subcomponent materials. Where designed to be soldered at high temperatures, NXP "Lead-free" products are suitable for use in specified "Lead-free" processes. This status is based on NXP's understanding of RoHS and NXP's knowledge of the materials that go into its products as of the date of disclosure of information.

To facilitate customer requirements to check compliance of the products of NXP Semiconductors, NXP has made the material content information available via the internet via: http://www.nxp.com/search/chemical_content/index.php

When reviewing the material content, a spreadsheet can be downloaded, for your convenience and further processing in chemical management systems like IMDS. Due to the availability of this service, it's NXP policy not to upload such material content data in customer systems.

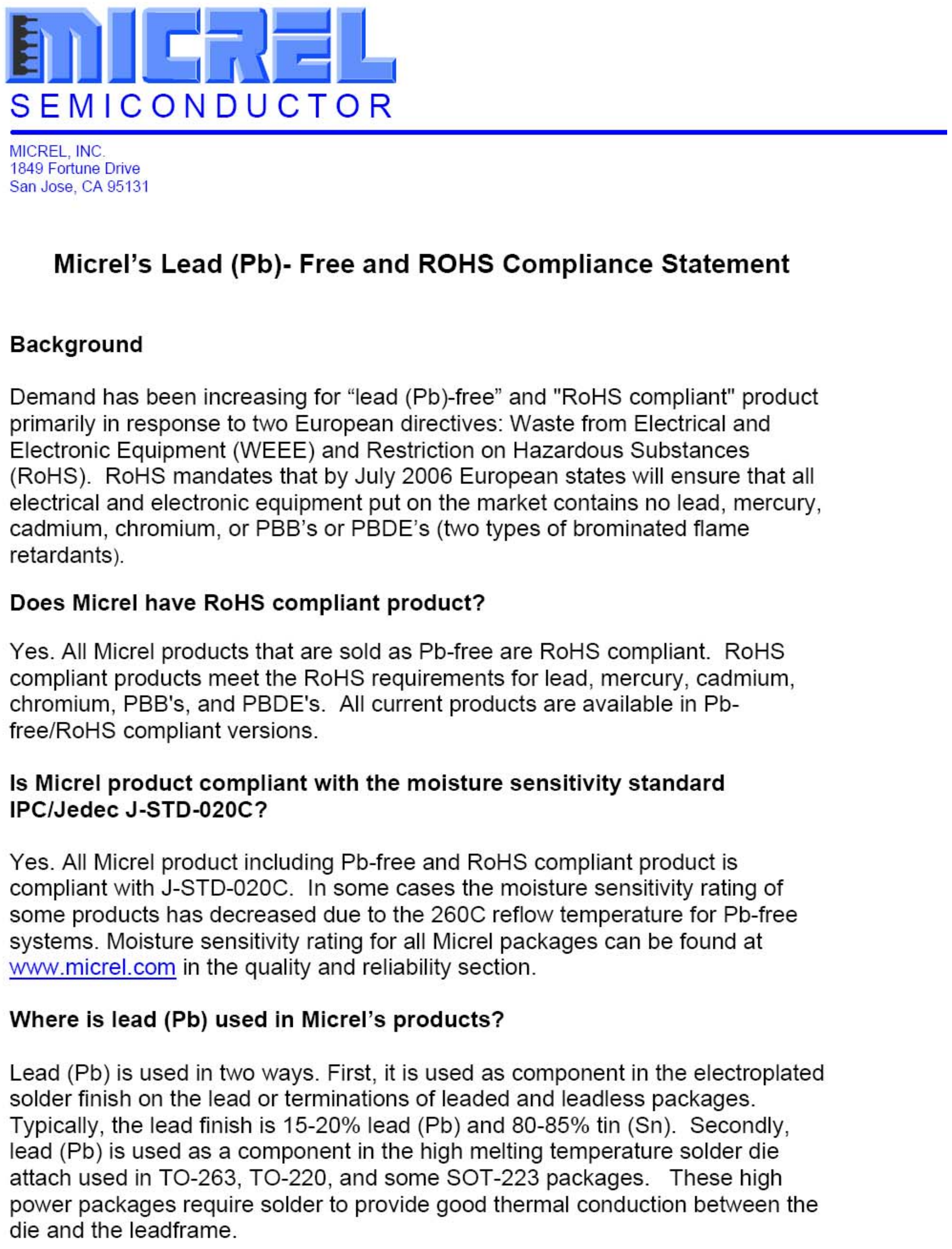
The signature below verifies that statements above, including but not limited to any material composition data are, to the best of our knowledge, valid and accurate. However, NXP cannot warrant that products from NXP's customers, in which such NXP products are incorporated, will in turn comply with this RoHS Declaration.

NXP Semiconductors
Sustainability Office

Eric-Paul Schat
Senior Director & Sustainability Officer

NXP Semiconductors, Sustainability Office, High Tech Campus 60, 5656AG Eindhoven, The Netherlands
Tel: +31 40 27 28355, Fax: +31 27 29961, www.nxp.com

DECLARATION LETTER FROM MICREL



MICREL SEMICONDUCTOR

MICREL, INC.
1849 Fortune Drive
San Jose, CA 95131

Micrel's Lead (Pb)- Free and ROHS Compliance Statement

Background

Demand has been increasing for "lead (Pb)-free" and "RoHS compliant" product primarily in response to two European directives: Waste from Electrical and Electronic Equipment (WEEE) and Restriction on Hazardous Substances (RoHS). RoHS mandates that by July 2006 European states will ensure that all electrical and electronic equipment put on the market contains no lead, mercury, cadmium, chromium, or PBB's or PBDE's (two types of brominated flame retardants).

Does Micrel have RoHS compliant product?

Yes. All Micrel products that are sold as Pb-free are RoHS compliant. RoHS compliant products meet the RoHS requirements for lead, mercury, cadmium, chromium, PBB's, and PBDE's. All current products are available in Pb-free/RoHS compliant versions.

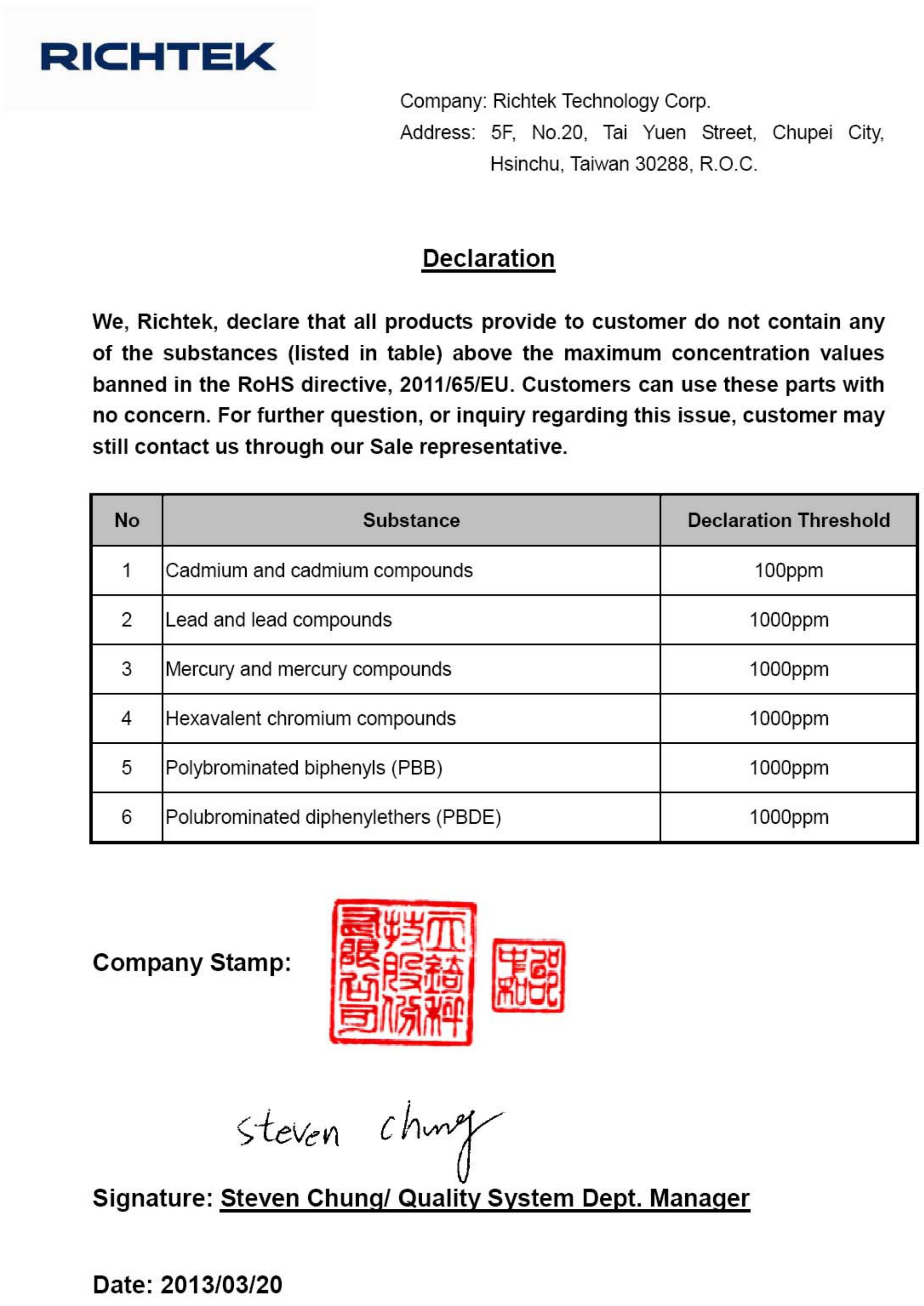
Is Micrel product compliant with the moisture sensitivity standard IPC/Jedec J-STD-020C?

Yes. All Micrel product including Pb-free and RoHS compliant product is compliant with J-STD-020C. In some cases the moisture sensitivity rating of some products has decreased due to the 260C reflow temperature for Pb-free systems. Moisture sensitivity rating for all Micrel packages can be found at www.micrel.com in the quality and reliability section.

Where is lead (Pb) used in Micrel's products?

Lead (Pb) is used in two ways. First, it is used as component in the electroplated solder finish on the lead or terminations of leaded and leadless packages. Typically, the lead finish is 15-20% lead (Pb) and 80-85% tin (Sn). Secondly, lead (Pb) is used as a component in the high melting temperature solder die attach used in TO-263, TO-220, and some SOT-223 packages. These high power packages require solder to provide good thermal conduction between the die and the leadframe.

DECLARATION LETTER FROM RICHTEK



RICHTEK

Company: Richtek Technology Corp.
Address: 5F, No.20, Tai Yuen Street, Chupei City,
Hsinchu, Taiwan 30288, R.O.C.

Declaration

We, Richtek, declare that all products provide to customer do not contain any of the substances (listed in table) above the maximum concentration values banned in the RoHS directive, 2011/65/EU. Customers can use these parts with no concern. For further question, or inquiry regarding this issue, customer may still contact us through our Sale representative.

No	Substance	Declaration Threshold
1	Cadmium and cadmium compounds	100ppm
2	Lead and lead compounds	1000ppm
3	Mercury and mercury compounds	1000ppm
4	Hexavalent chromium compounds	1000ppm
5	Polybrominated biphenyls (PBB)	1000ppm
6	Polubrominated diphenylethers (PBDE)	1000ppm

Company Stamp: 立錡科技股份有限公司 邰中和

steven chung

Signature: Steven Chung/ Quality System Dept. Manager

Date: 2013/03/20

APPENDIX II

PHOTOGRAPHAS